16 Mbit Concurrent SuperFlash + 2/4/8 Mbit (P)SRAM ComboMemory
SST34HF1621C / SST34HF1641J
SST34HF1641C / SST34HF1681J

Data Sheet

FEATURES:

- **Flash Organization: 1M x16 or 2M x8**
- **Dual-Bank Architecture for Concurrent Read/Write Operation**
  - Bottom Sector Protection
  - 16 Mbit: 12 Mbit + 4 Mbit
- **(P)SRAM Organization:**
  - 2 Mbit: 128K x16
  - 4 Mbit: 256K x16
  - 8 Mbit: 512K x16
- **Single 2.7-3.3V Read and Write Operations**
- **Superior Reliability**
  - Endurance: 100,000 Cycles (typical)
  - Greater than 100 years Data Retention
- **Low Power Consumption:**
  - Active Current: 25 mA (typical)
  - SRAM Standby Current: 20 µA (typical)
  - PSRAM Standby Current: 40 µA (typical)
- **Hardware Sector Protection (WP#)**
  - Protects 4 outer most sectors (4 KWord) in the larger bank by holding WP# low and unprotects by holding WP# high
- **Hardware Reset Pin (RST#)**
  - Resets the internal state machine to reading data array
- **Byte Selection for Flash (CIOF pin)**
  - Selects 8-bit or 16-bit mode (56-ball package only)
- **Sector-Erase Capability**
  - Uniform 2 KWord sectors
- **Block-Erase Capability**
  - Uniform 32 KWord blocks
- **Read Access Time**
  - Flash: 70 ns
  - (P)SRAM: 70 ns
- **Erase-Suspend / Erase-Resume Capabilities**
- **Security ID Feature**
  - SST: 128 bits
  - User: 128 bits
- **Latched Address and Data**
- **Fast Erase and Program (typical):**
  - Sector-Erase Time: 18 ms
  - Block-Erase Time: 18 ms
  - Chip-Erase Time: 35 ms
  - Program Time: 7 µs
- **Automatic Write Timing**
  - Internal V_{PP} Generation
- **End-of-Write Detection**
  - Toggle Bit
  - Data# Polling
  - Ready/Busy# pin
- **CMOS I/O Compatibility**
- **JEDEC Standard Command Set**
- **Packages Available**
  - 56-ball LFBGA (8mm x 10mm)
  - 62-ball LFBGA (8mm x 10mm)
- **All non-Pb (lead-free) devices are RoHS compliant**

PRODUCT DESCRIPTION

The SST34HF16x1C/J ComboMemory devices integrate either a 1M x16 or 2M x8 CMOS flash memory bank with either a 128K x16, 256K x16, or 512K x16 CMOS SRAM or pseudo SRAM (PSRAM) memory bank in a multi-chip package (MCP). These devices are fabricated using SST's proprietary, high-performance CMOS SuperFlash technology incorporating the split-gate cell design and thick-oxide tunneling injector to attain better reliability and manufacturability compared with alternate approaches. The SST34HF16x1C/J devices are ideal for applications such as cellular phones, GPS devices, PDAs, and other portable electronic devices in a low power and small form factor system.

The SST34HF16x1C/J feature dual flash memory bank architecture allowing for concurrent operations between the two flash memory banks and the (P)SRAM. The devices can read data from either bank while an Erase or Program operation is in progress in the opposite bank. The two flash memory banks are partitioned into 12 Mbit and 4 Mbit with bottom sector protection options for storing boot code, program code, configuration/parameter data and user data.

The SuperFlash technology provides fixed Erase and Program times, independent of the number of Erase/Program cycles that have occurred. Therefore, the system software or hardware does not have to be modified or de-rated as is necessary with alternative flash technologies, whose Erase and Program times increase with accumulated Erase/Program cycles. The SST34HF16x1C/J devices offer a guaranteed endurance of 10,000 cycles. Data retention is rated at greater than 100 years. With high-performance Program operations, the flash memory banks provide a typical Program time of 7 µsec. The entire flash memory bank can be erased and programmed word-by-word in typically 4 seconds for the SST34HF16x1C/J, when using interface fea-

tures such as Toggle Bit, Data# Polling, or RY/BY# to indicate the completion of Program operation. To protect against inadvertent flash write, the SST34HF16x1C/J devices contain on-chip hardware and software data protection schemes.

The flash and (P)SRAM operate as two independent memory banks with respective bank enable signals. The memory bank selection is done by two bank enable signals. The (P)SRAM bank enable signals, BES1# and BES2, select the (P)SRAM bank. The flash memory bank enable signal, BEF#, has to be used with Software Data Protection (SDP) command sequence when controlling the Erase and Program operations in the flash memory bank. The memory banks are superimposed in the same memory address space where they share common address lines, data lines, WE# and OE# which minimize power consumption and area.

Designed, manufactured, and tested for applications requiring low power and small form factor, the SST34HF16x1C/J are offered in extended temperatures and a small footprint package to meet board space constraint requirements. See Figures 4 and 5 for pin assignments.

Device Operation

The SST34HF16x1C/J uses BES1#, BES2 and BEF# to control operation of either the flash or the (P)SRAM memory bank. When BEF# is low, the flash bank is activated for Read, Program or Erase operation. When BES1# is low, and BES2 is high the (P)SRAM is activated for Read and Write operation. BEF# and BES1# cannot be at low level, and BES2 cannot be at high level at the same time. **If all bank enable signals are asserted, bus contention will result and the device may suffer permanent damage.** All address, data, and control lines are shared by flash and (P)SRAM memory banks which minimizes power consumption and loading. The device goes into standby when BEF# and BES1# bank enables are raised to V_{IHC} (Logic High) or when BEF# is high and BES2 is low.

Concurrent Read/Write Operation

Dual bank architecture of SST34HF16x1C/J devices allows the Concurrent Read/Write operation whereby the user can read from one bank while programming or erasing in the other bank. This operation can be used when the user needs to read system code in one bank while updating data in the other bank. See Figures 2 and 3 for dual-bank memory organization.

Concurrent Read/Write States

Flash		
Bank 1	**Bank 2**	**(P)SRAM**
Read	Write	No Operation
Write	Read	No Operation
Write	No Operation	Read
No Operation	Write	Read
Write	No Operation	Write
No Operation	Write	Write

Note: For the purposes of this table, Write means to perform Block-/Sector-Erase or Program operations as applicable to the appropriate bank.

Flash Read Operation

The Read operation of the SST34HF16x1C/J is controlled by BEF# and OE#, both have to be low for the system to obtain data from the outputs. BEF# is used for device selection. When BEF# is high, the chip is deselected and only standby power is consumed. OE# is the output control and is used to gate data from the output pins. The data bus is in high impedance state when either BEF# or OE# is high. Refer to the Read cycle timing diagram for further details (Figure 9).

Flash Program Operation

These devices are programmed on a word-by-word or byte-by-byte basis depending on the state of the CIOF pin. Before programming, one must ensure that the sector which is being programmed is fully erased.

The Program operation is accomplished in three steps:

1. Software Data Protection is initiated using the three-byte load sequence.
2. Address and data are loaded.

   During the Program operation, the addresses are latched on the falling edge of either BEF# or WE#, whichever occurs last. The data is latched on the rising edge of either BEF# or WE#, whichever occurs first.
3. The internal Program operation is initiated after the rising edge of the fourth WE# or BEF#, whichever occurs first. The Program operation, once initiated, will be completed typically within 7 µs.

See Figures 10 and 11 for WE# and BEF# controlled Program operation timing diagrams and Figure 24 for flowcharts. During the Program operation, the only valid reads are Data# Polling and Toggle Bit. During the internal Program operation, the host is free to perform additional tasks. Any commands issued during an internal Program operation are ignored.

Flash Sector- /Block-Erase Operation

These devices offer both Sector-Erase and Block-Erase operations. These operations allow the system to erase the devices on a sector-by-sector (or block-by-block) basis. The sector architecture is based on a uniform sector size of 2 KWord. The Block-Erase mode is based on a uniform block size of 32 KWord. The Sector-Erase operation is initiated by executing a six-byte command sequence with a Sector-Erase command (30H) and sector address (SA) in the last bus cycle. The Block-Erase operation is initiated by executing a six-byte command sequence with Block-Erase command (50H) and block address (BA) in the last bus cycle. The sector or block address is latched on the falling edge of the sixth WE# pulse, while the command (30H or 50H) is latched on the rising edge of the sixth WE# pulse. The internal Erase operation begins after the sixth WE# pulse. Any commands issued during the Block- or Sector-Erase operation are ignored except Erase-Suspend and Erase-Resume. See Figures 15 and 16 for timing waveforms.

Flash Chip-Erase Operation

The SST34HF16x1C/J provide a Chip-Erase operation, which allows the user to erase all sectors/blocks to the “1” state. This is useful when the device must be quickly erased.

The Chip-Erase operation is initiated by executing a six-byte command sequence with Chip-Erase command (10H) at address 555H in the last byte sequence. The Erase operation begins with the rising edge of the sixth WE# or BEF#, whichever occurs first. During the Erase operation, the only valid read is Toggle Bits or Data# Polling. See Table 5 for the command sequence, Figure 14 for timing diagram, and Figure 28 for the flowchart. Any commands issued during the Chip-Erase operation are ignored. When WP# is low, any attempt to Chip-Erase will be ignored.

Flash Erase-Suspend/-Resume Operations

The Erase-Suspend operation temporarily suspends a Sector- or Block-Erase operation thus allowing data to be read from any memory location, or program data into any sector/block that is not suspended for an Erase operation. The operation is executed by issuing a one-byte command sequence with Erase-Suspend command (B0H). The device automatically enters read mode no more than 10 µs after the Erase-Suspend command had been issued. (T_{ES} maximum latency equals 10 µs.) Valid data can be read from any sector or block that is not suspended from an Erase operation. Reading at address location within erase-suspended sectors/blocks will output DQ_2 toggling and DQ_6 at “1”. While in Erase-Suspend mode, a Program operation is allowed except for the sector or block selected for Erase-Suspend. To resume Sector-Erase or Block-Erase operation which has been suspended, the system must issue an Erase-Resume command. The operation is executed by issuing a one-byte command sequence with Erase Resume command (30H) at any address in the one-byte sequence.

Flash Write Operation Status Detection

The SST34HF16x1C/J provide one hardware and two software means to detect the completion of a Write (Program or Erase) cycle, in order to optimize the system Write cycle time. The hardware detection uses the Ready/Busy# (RY/BY#) pin. The software detection includes two status bits: Data# Polling (DQ_7) and Toggle Bit (DQ_6). The End-of-Write detection mode is enabled after the rising edge of WE#, which initiates the internal Program or Erase operation.

The actual completion of the nonvolatile write is asynchronous with the system; therefore, either a Ready/Busy# (RY/BY#), Data# Polling (DQ_7) or Toggle Bit (DQ_6) read may be simultaneous with the completion of the Write cycle. If this occurs, the system may possibly get an erroneous result, i.e., valid data may appear to conflict with either DQ_7 or DQ_6. In order to prevent spurious rejection, if an erroneous result occurs, the software routine should include a loop to read the accessed location an additional two (2) times. If both reads are valid, then the device has completed the Write cycle, otherwise the rejection is valid.

Ready/Busy# (RY/BY#)

The SST34HF16x1C/J include a Ready/Busy# (RY/BY#) output signal. RY/BY# is an open drain output pin that indicates whether an Erase or Program operation is in progress. Since RY/BY# is an open drain output, it allows several devices to be tied in parallel to V_{DD} via an external pull-up resistor. After the rising edge of the final WE# pulse in the command sequence, the RY/BY# status is valid.

When RY/BY# is actively pulled low, it indicates that an Erase or Program operation is in progress. When RY/BY# is high (Ready), the devices may be read or left in standby mode.

Byte/Word (CIOF)

This function, found only on the 56-ball package, includes a CIOF pin to control whether the device data I/O pins operate x8 or x16. If the CIOF pin is at logic "1" (V_{IH}) the device is in x16 data configuration: all data I/0 pins DQ_0-DQ_{15} are active and controlled by BEF# and OE#.

If the CIOF pin is at logic "0", the device is in x8 data configuration: only data I/O pins DQ_0-DQ_7 are active and controlled by BEF# and OE#. The remaining data pins DQ_8-DQ_{14} are at Hi-Z, while pin DQ_{15} is used as the address input A_{-1} for the Least Significant Bit of the address bus.

Flash Data# Polling (DQ_7)

When the devices are in an internal Program operation, any attempt to read DQ_7 will produce the complement of the true data. Once the Program operation is completed, DQ_7 will produce true data. During internal Erase operation, any attempt to read DQ_7 will produce a '0'. Once the internal Erase operation is completed, DQ_7 will produce a '1'. The Data# Polling is valid after the rising edge of fourth WE# (or BEF#) pulse for Program operation. For Sector-, Block-, or Chip-Erase, the Data# Polling is valid after the rising edge of sixth WE# (or BEF#) pulse. See Figure 12 for Data# Polling (DQ_7) timing diagram and Figure 25 for a flowchart.

Toggle Bits (DQ_6 and DQ_2)

During the internal Program or Erase operation, any consecutive attempts to read DQ_6 will produce alternating "1"s and "0"s, i.e., toggling between 1 and 0. When the internal Program or Erase operation is completed, the DQ_6 bit will stop toggling. The device is then ready for the next operation. The toggle bit is valid after the rising edge of the fourth WE# (or BEF#) pulse for Program operations. For Sector-, Block-, or Chip-Erase, the toggle bit (DQ_6) is valid after the rising edge of sixth WE# (or BEF#) pulse. DQ_6 will be set to "1" if a Read operation is attempted on an Erase-suspended Sector/Block. If Program operation is initiated in a sector/block not selected in Erase-Suspend mode, DQ_6 will toggle.

An additional Toggle Bit is available on DQ_2, which can be used in conjunction with DQ_6 to check whether a particular sector is being actively erased or erase-suspended. Table 1 shows detailed status bit information. The Toggle Bit (DQ_2) is valid after the rising edge of the last WE# (or BEF#) pulse of a Write operation. See Figure 13 for Toggle Bit timing diagram and Figure 25 for a flowchart.

TABLE 1: Write Operation Status

Status		DQ_7	DQ_6	DQ_2	RY/BY#
Normal Operation	Standard Program	DQ7#	Toggle	No Toggle	0
	Standard Erase	0	Toggle	Toggle	0
Erase-Suspend Mode	Read From Erase Suspended Sector/Block	1	1	Toggle	1
	Read From Non-Erase Suspended Sector/Block	Data	Data	Data	1
	Program	DQ7#	Toggle	No Toggle	0

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Note: DQ_7, DQ_6, and DQ_2 require a valid address when reading status information. The address must be in the bank where the operation is in progress in order to read the operation status. If the address is pointing to a different bank (not busy), the device will output array data.

Data Protection

The SST34HF16x1C/J provide both hardware and software features to protect nonvolatile data from inadvertent writes.

Hardware Data Protection

Noise/Glitch Protection: A WE# or BEF# pulse of less than 5 ns will not initiate a Write cycle.

V_{DD} Power Up/Down Detection: The Write operation is inhibited when V_{DD} is less than 1.5V.

Write Inhibit Mode: Forcing OE# low, BEF# high, or WE# high will inhibit the Write operation. This prevents inadvertent writes during power-up or power-down.

Hardware Block Protection

The SST34HF16x1C/J provide a hardware block protection which protects the outermost 8 KWord in Bank 1. The block is protected when WP# is held low. See Figures 2 and 3 for Block-Protection location.

A user can disable block protection by driving WP# high thus allowing erase or program of data into the protected sectors. WP# must be held high prior to issuing the write command and remain stable until after the entire Write operation has completed. If WP# is left floating, it is internally held high via a pull-up resistor, and the Boot Block is unprotected, enabling Program and Erase operations on that block.

Hardware Reset (RST#)

The RST# pin provides a hardware method of resetting the device to read array data. When the RST# pin is held low for at least T_{RP}, any in-progress operation will terminate and return to Read mode, see Figure 21. When no internal Program/Erase operation is in progress, a minimum period of T_{RHR} is required after RST# is driven high before a valid Read can take place, see Figure 20.

The Erase operation that has been interrupted needs to be reinitiated after the device resumes normal operation mode to ensure data integrity. See Figures 20 and 21 for timing diagrams.

Software Data Protection (SDP)

The SST34HF16x1C/J provide the JEDEC standard Software Data Protection scheme for all data alteration operations, i.e., Program and Erase. Any Program operation requires the inclusion of the three-byte sequence. The three-byte load sequence is used to initiate the Program operation, providing optimal protection from inadvertent Write operations, e.g., during the system power-up or power-down. Any Erase operation requires the inclusion of six-byte sequence. The SST34HF16x1C/J are shipped with the Software Data Protection permanently enabled. See Table 5 for the specific software command codes. During SDP command sequence, invalid commands will abort the device to Read mode within T_{RC}. The contents of DQ_{15}-DQ_8 are "Don't Care" during any SDP command sequence.

Common Flash Memory Interface (CFI)

These devices also contain the CFI information to describe the characteristics of the devices. In order to enter the CFI Query mode, the system must write the three-byte sequence same as the Software ID Entry command with 98H (CFI Query command) to address 555H in the last byte sequence. For CFI Entry and Bead timing diagram, See Figure 18. Once the device enters the CFI Query mode, the system can read CFI data a t the addresses given in Tables 7 and 9. The system must write the CFI Exit command to return to Bead mode from the CFI Query mode.

Security ID

The SST34HF16x1C/J devices offer a 256-bit Security ID space. The Secure ID space is divided into two 128-bit segments—one factory programmed segment and one user programmed segment. The first segment is programmed and locked at SST with a unique, 128-bit number. The user segment is left un-programmed for the customer to program as desired. To program the user segment of the Security ID, the user must use the Security ID Program command. End-of-Write status is checked by reading the toggle bits. Data# Polling is not used for Security ID End-of-Write detection. Once programming is complete, the Sec ID should be locked using the User-Sec-ID-Program-Lock-Out. This disables any future corruption of this space. Note that regardless of whether or not the Sec ID is locked, neither Sec ID segment can be erased. The Secure ID space can be queried by executing a three-byte command sequence with Query-Sec-ID command (88H) at address 555H in the last byte sequence. To exit this mode, the Exit-Sec-ID command should be executed. Refer to Table 5 for more details.

Product Identification

The Product Identification mode identifies the device as the SST34HF16x1C/J and manufacturer as SST. This mode may be accessed by software operations only. The hardware device ID Read operation, which is typically used by programmers cannot be used on this device because of the shared lines between flash and (P)SRAM in the multi-chip package. Therefore, application of high voltage to pin A_9 may damage this device. Users may use the software Product Identification operation to identify the part (i.e., using the device ID) when using multiple manufacturers in the same socket. For details, see Tables 4 and 5 for software operation, Figure 17 for the Software ID Entry and Read timing diagram and Figure 26 for the ID Entry command sequence flowchart.

TABLE 2: Product Identification

	ADDRESS	DATA
Manufacturer's ID	BK0000H	00BFH
Device ID		
SST34HF16x1C/J	BK0001H	734BH

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Note: BK = Bank Address (A_{19}-A_{18})

Product Identification Mode Exit

In order to return to the standard Read mode, the Software Product Identification mode must be exited. Exit is accomplished by issuing the Software ID Exit command sequence, which returns the device to the Read mode. This command may also be used to reset the device to the Read mode after any inadvertent transient condition that apparently causes the device to behave abnormally, e.g., not read correctly. Note that the Software ID Exit/CFI Exit command is ignored during an internal Program or Erase operation. See Table 5 for software command codes, Figure 19 for timing waveform and Figure 26 for a flowchart.

(P)SRAM Operation

With BES1# low, BES2 and BEF# high, the SST34HF16x1C/J operate as either 128K x16, 256K x16, or 512K x16 CMOS (P)SRAM, with fully static operation requiring no external clocks or timing strobes. The SST34HF16x1C/J (P)SRAM is mapped into the first 512 KWord address space. When BES1#, BEF# are high and BES2 is low, all memory banks are deselected and the device enters standby. Read and Write cycle times are equal. The control signals UBS# and LBS# provide access to the upper data byte and lower data byte. For (P)SRAM Read and Write data byte control modes of operation, see Table 4.

(P)SRAM Read

The (P)SRAM Read operation of the SST34HF16x1C/J/S is controlled by OE# and BES1#, both have to be low with WE# and BES2 high for the system to obtain data from the outputs. BES1# and BES2 are used for (P)SRAM bank selection. OE# is the output control and is used to gate data from the output pins. The data bus is in high impedance state when OE# is high. Refer to the Read cycle timing diagram, Figure 6, for further details.

(P)SRAM Write

The (P)SRAM Write operation of the SST34HF16x1C/J/S is controlled by WE# and BES1#, both have to be low, BES2 must be high for the system to write to the (P)SRAM. During the Word-Write operation, the addresses and data are referenced to the rising edge of either BES1#, WE#, or the falling edge of BES2 whichever occurs first. The write time is measured from the last falling edge of BES#1 or WE# or the rising edge of BES2 to the first rising edge of BES1#, or WE# or the falling edge of BES2. Refer to the Write cycle timing diagrams, Figures 7 and 8, for further details.

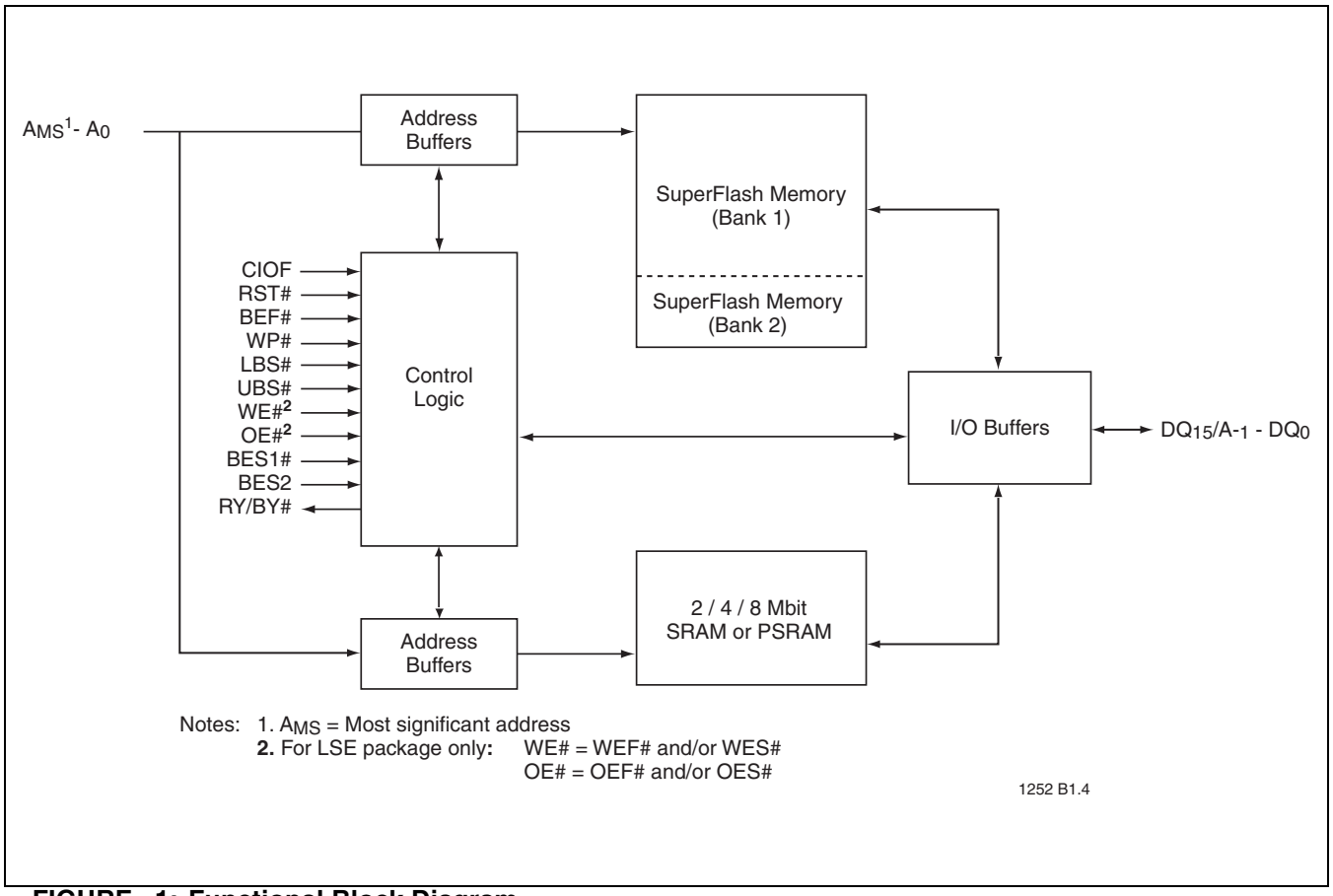

FIGURE 1: Functional Block Diagram

Bottom Sector Protection; 32 KWord Blocks; 2 KWord Sectors

FFFFFH F8000H	Block 31	Bank 2
F7FFFH F0000H	Block 30	
EFFFFH E8000H	Block 29	
E7FFFH E0000H	Block 28	
DFFFFH D8000H	Block 27	
D7FFFH D0000H	Block 26	
CFFFFH C8000H	Block 25	
C7FFFH C0000H	Block 24	
BFFFFH B8000H	Block 23	Bank 1
B7FFFH B0000H	Block 22	
AFFFFH A8000H	Block 21	
A7FFFH A0000H	Block 20	
9FFFFH 98000H	Block 19	
97FFFH 90000H	Block 18	
8FFFFH 88000H	Block 17	
87FFFH 80000H	Block 16	
7FFFFH 78000H	Block 15	
77FFFH 70000H	Block 14	
6FFFFH 68000H	Block 13	
67FFFH 60000H	Block 12	
5FFFFH 58000H	Block 11	
57FFFH 50000H	Block 10	
4FFFFH 48000H	Block 9	
47FFFH 40000H	Block 8	
3FFFFH 38000H	Block 7	
37FFFH 30000H	Block 6	
2FFFFH 28000H	Block 5	
27FFFH 20000H	Block 4	
1FFFFH 18000H	Block 3	
17FFFH 10000H	Block 2	
0FFFFH 08000H	Block 1	
07FFFH 02000H	Block 0	
01FFFH 00000H		

8 KWord Sector Protection (4-2 KWord Sectors)

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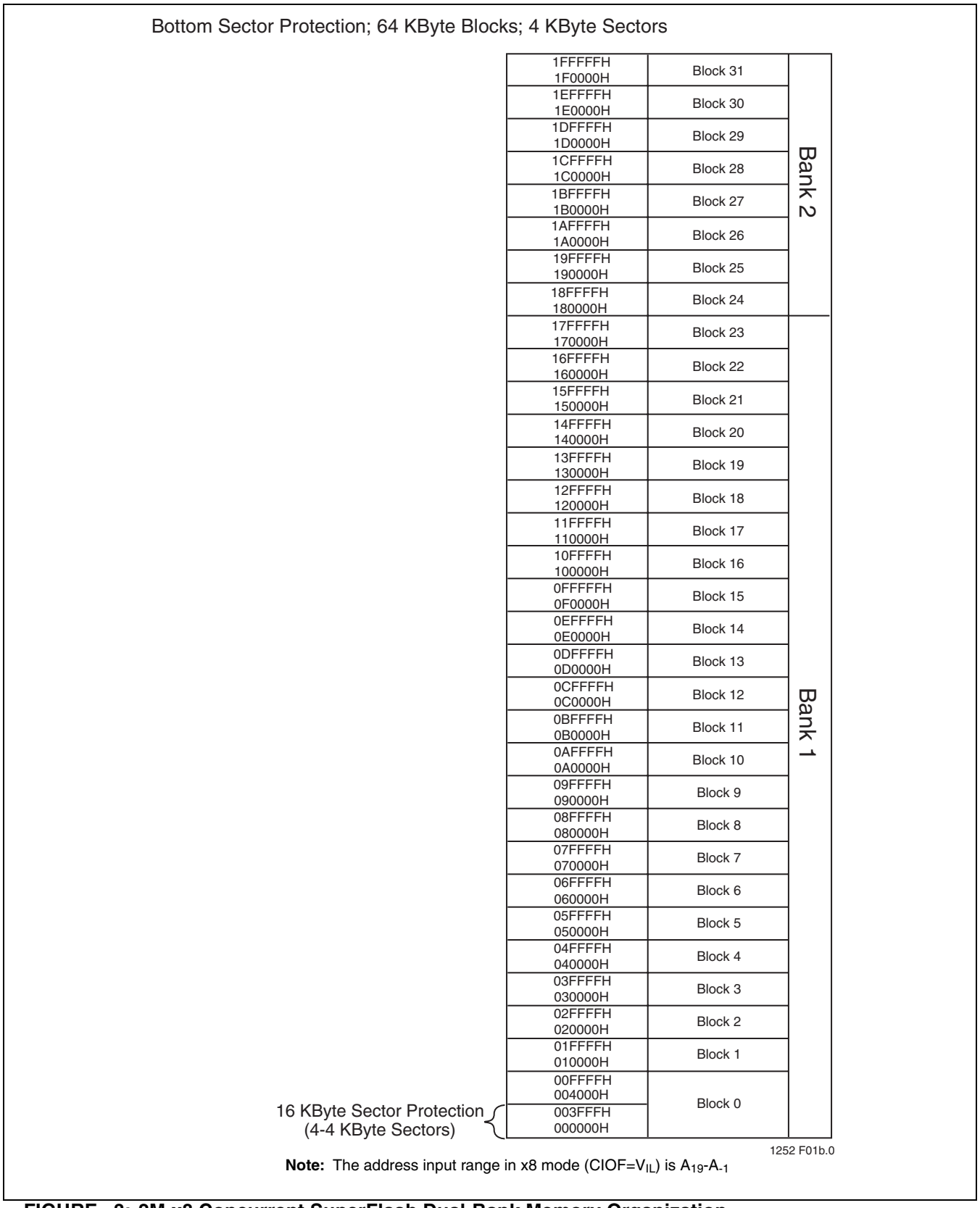
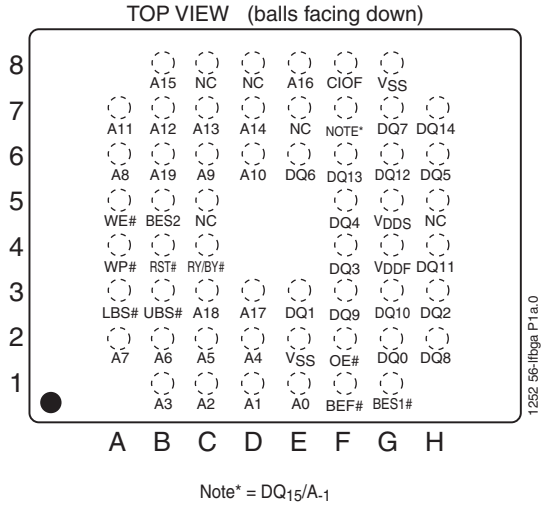
Note: The address input range in x16 mode (COIF=V_{IH}) is A_{19}-A_0

FIGURE 2: 1M x16 Concurrent SuperFlash Dual-Bank Memory Organization



Note: The address input range in x8 mode (CIOF=V_{IL}) is A_{19}-A_{-1}

FIGURE 3: 2M x8 Concurrent SuperFlash Dual-Bank Memory Organization



Note* = DQ_{15}/A_{-1}

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FIGURE 4: Pin Assignments for 56-ball LFBGA (8mm x 10mm)

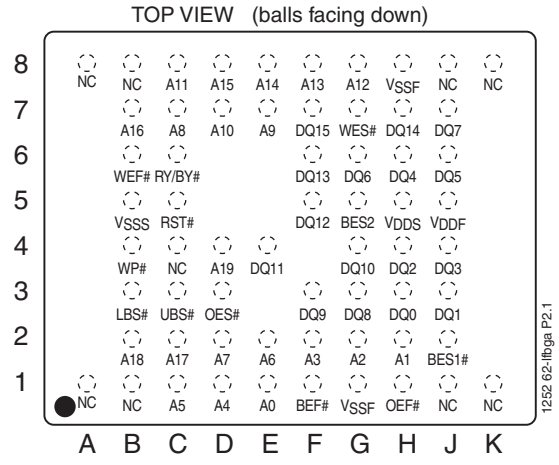

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FIGURE 5: Pin Assignments for 62-ball LFBGA (8mm x 10mm)

TABLE 3: Pin Description

Symbol	Pin Name	Functions
A_{MS}[1] to A_0	Address Inputs	To provide flash address, A_{19}-A_0. To provide (P)SRAM address, A_{MS}-A_0
DQ_{14}-DQ_0	Data Inputs/Outputs	To output data during Read cycles and receive input data during Write cycles. Data is internally latched during a flash Erase/Program cycle. The outputs are in tri-state when OE# is high or BES1# is high or BES2 is low and BEF# is high.
DQ_{15}/A_{-1}	Data Input/Output and LBS Address	DQ_{15} is used as data I/O pin when in x16 mode (CIOF = "1") A_{-1} is used as the LBS address pin when in x8 mode (CIOF = "0")
BEF#	Flash Memory Bank Enable	To activate the Flash memory bank when BEF# is low
BES1#	(P)SRAM Memory Bank Enable	To activate the (P)SRAM memory bank when BES1# is low
BES2	(P)SRAM Memory Bank Enable	To activate the (P)SRAM memory bank when BES2 is high
OEF#[2]	Output Enable	To gate the data output buffers for Flash[2] only
OES#[2]	Output Enable	To gate the data output buffers for SRAM[2] only
WEF#[2]	Write Enable	To control the Write operations for Flash[2] only
WES#[2]	Write Enable	To control the Write operations for SRAM[2] only
OE#	Output Enable	To gate the data output buffers
WE#	Write Enable	To control the Write operations
CIOF[3]	Byte Selection for Flash	When low, select Byte mode. When high, select Word mode.
UBS#	Upper Byte Control ((P)SRAM)	To enable DQ_{15}-DQ_8
LBS#	Lower Byte Control ((P)SRAM)	To enable DQ_7-DQ_0
WP#	Write Protect	To protect and unprotect the bottom 8 KWord (4 sectors) from Erase or Program operation
RST#	Reset	To Reset and return the device to Read mode
RY/BY#	Ready/Busy#	To output the status of a Program or Erase Operation RY/BY# is a open drain output, so a 10KΩ - 100KΩ pull-up resistor is required to allow RY/BY# to transition high indicating the device is ready to read.
V_{SSF}[2]	Ground	Flash[2] only
V_{SSS}[2]	Ground	SRAM[2] only
V_{SS}	Ground	
V_{DDF}	Power Supply (Flash)	2.7-3.3V Power Supply to Flash only
V_{DDS}	Power Supply ((P)SRAM)	2.7-3.3V Power Supply to (P)SRAM only
NC	No Connection	Unconnected pins

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1. A_{MS} = Most Significant Address
   A_{MS} = A_{16} for SST34HF1621C, A_{17} for SST34HF1641C/J, and A_{18} for SST34HF1681J
2. LSE package only
3. L1PE package only

TABLE 4: Operational Modes Selection

Mode	BEF#[1]	BES1#[1,2]	BES2[1,2]	OE#[2,3]	WE#[2,3]	LBS#[2]	UBS#[2]	DQ_{15-8}		
								DQ_{7-0}	CIOF = V_{IH}	CIOF = V_{IL}
Full Standby	V_{IH}	V_{IH}	X	X	X	X	X	HIGH-Z	HIGH-Z	HIGH-Z
		X	V_{IL}	X	X	X	X			
Output Disable	V_{IH}	V_{IL}	V_{IH}	V_{IH}	V_{IH}	X	X	HIGH-Z	HIGH-Z	HIGH-Z
		V_{IL}	V_{IH}	X	X	V_{IH}	V_{IH}			
	V_{IL}	V_{IH}	X	V_{IH}	V_{IH}	X	X	HIGH-Z	HIGH-Z	HIGH-Z
		X	V_{IL}							
Flash Read	V_{IL}	V_{IH}	X	V_{IL}	V_{IH}	X	X	D_{OUT}	D_{OUT}	DQ_{14-8} = HIGH-Z DQ_{15} = A_{-1}
		X	V_{IL}							
Flash Write	V_{IL}	V_{IH}	X	V_{IH}	V_{IL}	X	X	D_{IN}	D_{IN}	DQ_{14-8} = HIGH-Z DQ_{15} = A_{-1}
		X	V_{IL}							
Flash Erase	V_{IL}	V_{IH}	X	V_{IH}	V_{IL}	X	X	X	X	X
		X	V_{IL}							
(P)SRAM Read	V_{IH}	V_{IL}	V_{IH}	V_{IL}	V_{IH}	V_{IL}	V_{IL}	D_{OUT}	D_{OUT}	D_{OUT}
						V_{IH}	V_{IL}	HIGH-Z	D_{OUT}	D_{OUT}
						V_{IL}	V_{IH}	D_{OUT}	HIGH-Z	HIGH-Z
(P)SRAM Write	V_{IH}	V_{IL}	V_{IH}	X	V_{IL}	V_{IL}	V_{IL}	D_{IN}	D_{IN}	D_{IN}
						V_{IH}	V_{IL}	HIGH-Z	D_{IN}	D_{IN}
						V_{IL}	V_{IH}	D_{IN}	HIGH-Z	HIGH-Z
Product Identification[4]	V_{IL}	V_{IH}	V_{IL}	V_{IL}	V_{IH}	X	X	Manufacturer's ID[5] Device ID[5]		

T4.1 1252

1. Do not apply BEF# = V_{IL}, BES1# = V_{IL} and BES2 = V_{IH} at the same time
2. X can be V_{IL} or V_{IH}, but no other value.
3. OE# = OEF# and OES#
   WE# = WEF# and WES# for LSE package only
4. Software mode only
5. With A_{19}-A_{18} = V_{IL};SST Manufacturer's ID = BFH, is read with A_0=0,
   SST34HF16x1C/J Device ID = 734BH, is read with A_0=1

TABLE 5: Software Command Sequence

Command Sequence	1st Bus Write Cycle		2nd Bus Write Cycle		3rd Bus Write Cycle		4th Bus Write Cycle		5th Bus Write Cycle		6th Bus Write Cycle	
	Addr[1]	Data[2]	Addr[1]	Data[2]	Addr[1]	Data[2]	Addr[1]	Data[2]	Addr[1]	Data[2]	Addr[1]	Data[2]
Program	555H	AAH	2AAH	55H	555H	A0H	WA[3]	Data				
Sector-Erase	555H	AAH	2AAH	55H	555H	80H	555H	AAH	2AAH	55H	SA_X[4]	30H
Block-Erase	555H	AAH	2AAH	55H	555H	80H	555H	AAH	2AAH	55H	BA_X[4]	50H
Chip-Erase	555H	AAH	2AAH	55H	555H	80H	555H	AAH	2AAH	55H	555H	10H
Erase-Suspend	XXXXH	B0H										
Erase-Resume	XXXXH	30H										
Query Sec ID[5]	555H	AAH	2AAH	55H	555H	88H						
User Security ID Program	555H	AAH	2AAH	55H	555H	A5H	SIWA[6]	Data				
User Security ID Program Lock-out[7]	555H	AAH	2AAH	55H	555H	85H	XXH	0000H				
Software ID Entry[8]	555H	AAH	2AAH	55H	BK_X[9] 555H	90H						
CFI Query Entry	555H	AAH	2AAH	55H	BK_X[9] 555H	98H						
Software ID Exit/ CFI Exit Sec ID Exit[10,11]	555H	AAH	2AAH	55H	555H	F0H						
Software ID Exit/ CFI Exit Sec ID Exit[10,11]	XXH	F0H										

T5.4 1252

1. Address format A_{10}-A_0 (Hex), Addresses A_{19}-A_{11} can be V_{IL} or V_{IH}, but no other value, for the command sequence when in x16 mode. When in x8 mode, Addresses A_{19}-A_{12}, Address A_{-1} and DQ_{14}-DQ_8 can be V_{IL} or V_{IH}, but no other value, for the command sequence.
2. DQ_{15}-DQ_8 can be V_{IL} or V_{IH}, but no other value, for the command sequence
3. WA = Program word/byte address
4. SA_X for Sector-Erase; uses A_{19}-A_{11} address lines
   BA_X for Block-Erase; uses A_{19}-A_{15} address lines
5. For SST34HF16x1C/J,
   SST ID is read with A_4 = 0 (Address range = 00000H to 00007H),
   User ID is read with A_4 = 1 (Address range = 00010H to 00017H).
   Lock Status is read with A_7-A_0 = 000FFH. Unlocked: DQ_3 = 1 / Locked: DQ_3 = 0.
6. SIWA = User Security ID Program word/byte address
   For SST34HF16x1C/J, valid Word-Addresses for User Sec ID are from 00010H-00017H.
   All 4 cycles of User Security ID Program and Program Lock-out must be completed before going back to Read-Array mode.
7. The User Security ID Program Lock-out command must be executed in x16 mode (CIOF=V_{IH}).
8. The device does not remain in Software Product Identification mode if powered down.
9. A_{19} and A_{18} = V_{IL}
10. Both Software ID Exit operations are equivalent
11. If users never lock after programming, User Sec ID can be programmed over the previously unprogrammed bits (data=1) using the User Sec ID mode again (the programmed “0” bits cannot be reversed to “1”).
    For SST34HF16x1C/J, valid Word-Addresses for User Sec ID are from 00010H-00017H.

TABLE 6: CFI QUERY IDENTIFICATION STRING[1]

Address x16 Mode	Address x8 Mode	Data[2]	Description
10H 11H 12H	20H 22H 24H	0051H 0052H 0059H	Query Unique ASCII string “QRY”
13H 14H	26H 28H	001H 007H	Primary OEM command set
15H 16H	2AH 2CH	0000H 0000H	Address for Primary Extended Table
17H 18H	2EH 30H	0000H 0000H	Alternate OEM command set (00H = none exits)
19H 1AH	32H 34H	0000H 0000H	Address for Alternate OEM extended Table (00H - none exits)

T6.0 1252

1. Refer to CFI publication 100 for more details.
2. In x8 mode only the lower byte of data is output.

TABLE 7: SYSTEM INTERFACE INFORMATION

Address x16 Mode	Address x8 Mode	Data[1]	Description
1BH	36H	0027H	V_{DD} Min (Program/Erase) DQ_7-DQ_4: Volts, DQ_3-DQ_0: 100 Millivolts
1CH	38H	0036H	V_{DD} Max (Program/Erase) DQ_7-DQ_4: Volts, DQ_3-DQ_0: 100 Millivolts
1DH	3AH	0000H	V_{DD} Min (00H = No V_{DD} pin)
1EH	3CH	0000H	V_{DD} Max (00H = No V_{DD} pin)
1FH	3EHh	0004H	Typical time out for Program 2^N µs (2^4 = 16 µs)
20H	40H	0000H	Typical time out for min size buffer program 2^N µs (00H = not supported)
21H	42H	0004H	Typical time out for individual Sector-/Block-Erase 2^N ms (2^N = 16 ms)
22H	44H	0006H	Typical time out for Chip-Erase 2^N ms (2^6 = 64 ms)
23H	46H	0001H	Maximum time out for Program 2^N time typical (2^1 x 2^4 - 32 µs)
24H	48H	0000H	Maximum time out for buffer program 2^N time typical
25H	4AH	0001H	Maximum time out for individual Sector-Block-Erase 2^N time typical (2^1 x 2^4 - 32 ms)
26H	4CH	0001H	Maximum time out for individual Chip-Erase 2^N time typical (2^1 x 2^6 - 128 ms)

T7.0 1252

1. In x8 mode, only the lower byte of data is output.

TABLE 8: SYSTEM INTERFACE INFORMATION

Address x16 Mode	Address x8 Mode	Data[1]	Description
27H	4EH	0015H	Device size = 2^N Bytes (15H = 21; 2^{21} = 2 MByte)
28H	50H	0002H	Flash Device Interface description; 0002H = x8/x16 asynchronous interface
29H	52H	0000H	
2AH	54H	00000H	Maximum number of bytes in multi-byte write = 2^N (00H = not supported)
2BH	56H	0000H	
2CH	58H	0002H	Number of Erase Sector/Block sizes supported by device
2DH	5AH	00FFH	Sector Information (y + 1 = Number of sectors; z x 256B = sector size)
2EH	5CH	0001H	y = 511 + 1 = 512 sectors (01FFH = 512)
2FH	5EH	0010H	
30H	60H	0000H	z = 16 x 256 Bytes = 4 KByte/sector (0010H = 16)
31H	62H	001FH	Block Information (y + 1 = Number of blocks; z x 256B = block size)
32H	64H	0000H	y = 31 + 1 = 32 blocks (001FH = 31)
33H	66H	0000H	
34H	68H	0001H	z = 256 x 256 Bytes = 64 KByte/block (0100H = 256)

T8.0 1252

1. In x8 mode, only the lower byte of data is output.

Absolute Maximum Stress Ratings (Applied conditions greater than those listed under "Absolute Maximum Stress Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these conditions or conditions greater than those defined in the operational sections of this data sheet is not implied. Exposure to absolute maximum stress rating conditions may affect device reliability.)

Operating Temperature . . . . . -20°C to +85°C
Storage Temperature . . . . . -65°C to +125°C
D. C. Voltage on Any Pin to Ground Potential . . . . . -0.5V to V_{DD}[1]+0.3V
Transient Voltage (<20 ns) on Any Pin to Ground Potential . . . . . -1.0V to V_{DD}[1]+1.0V
Package Power Dissipation Capability (T_A = 25°C) 1.0W
Surface Mount Solder Reflow Temperature . . . . . 260°C for 10 seconds
Output Short Circuit Current[2] . . . . . 50 mA

1. V_{DD} = V_{DDF} and V_{DDS}
2. Outputs shorted for no more than one second. No more than one output shorted at a time.

Operating Range

Range	Ambient Temp	V_{DD}
Extended	-20°C to +85°C	2.7-3.3V

AC Conditions of Test

Input Rise/Fall Time . . . . . 5 ns
Output Load . . . . . C_L = 30 pF
See Figures 22 and 23

TABLE 9: DC Operating Characteristics (V_{DD} = V_{DDF} and V_{DDS} = 2.7-3.3V)

Symbol	Parameter	Limits			Test Conditions
		Min	Max	Units	
I_{DD}[1]	Active V_{DD} Current				Address input = V_{ILT}/V_{IHT}, at f=5 MHz, $V_{DD}=V_{DD}$ Max, all DQs open
	Read				OE#=V_{IL}, WE#=V_{IH}
	Flash		35	mA	BEF#=V_{IL}, BES1#=V_{IH}, or BES2=V_{IL}
	(P)SRAM		30	mA	BEF#=V_{IH}, BES1#=V_{IL} , BES2=V_{IH}
	Concurrent Operation		60	mA	BEF#=V_{IH}, BES1#=V_{IL} , BES2=V_{IH}
	Write[2]				WE#=V_{IL}
	Flash		40	mA	BEF#=V_{IL}, BES1#=V_{IH}, or BES2=V_{IL}, OE#=V_{IH}
	(P)SRAM		30	mA	BEF#=V_{IH}, BES1#=V_{IL} , BES2=V_{IH}
I_{SB}	Standby V_{DD} Current SRAM		30	µA	V_{DD} = V_{DD} Max, BEF#=BES1#=V_{IHC}, BES2=V_{ILC}
	PSRAM		85	µA	
I_{RT}	Reset V_{DD} Current		30	µA	RST#=GND
I_{LI}	Input Leakage Current		1	µA	V_{IN}=GND to V_{DD}, $V_{DD}=V_{DD}$ Max
I_{LIW}	Input Leakage Current on WP# pin and RST# pin		10	µA	WP#=GND to V_{DD}, $V_{DD}=V_{DD}$ Max RST#=GND to V_{DD}, $V_{DD}=V_{DD}$ Max
I_{LO}	Output Leakage Current		10	µA	V_{OUT}=GND to V_{DD}, $V_{DD}=V_{DD}$ Max
V_{IL}	Input Low Voltage		0.8	V	$V_{DD}=V_{DD}$ Min
V_{ILC}	Input Low Voltage (CMOS)		0.3	V	$V_{DD}=V_{DD}$ Max
V_{IH}	Input High Voltage	0.7 V_{DD}		V	$V_{DD}=V_{DD}$ Max
V_{IHC}	Input High Voltage (CMOS)	V_{DD}-0.3		V	$V_{DD}=V_{DD}$ Max
V_{OL}	Flash Output Low Voltage		0.2	V	I_{OL}=100 µA, $V_{DD}=V_{DD}$ Min
V_{OH}	Flash Output High Voltage	V_{DD}-0.2		V	I_{OH}=-100 µA, $V_{DD}=V_{DD}$ Min

T9.1 1252

1. Address input = V_{ILT}/V_{IHT}, $V_{DD}=V_{DD}$ Max (See Figure 22)
2. I_{DD} active while Erase or Program is in progress.

TABLE 10: Recommended System Power-up Timings

Symbol	Parameter	Minimum	Units
$T_{PU-READ}$[1]	Power-up to Read Operation	100	µs
$T_{PU-WRITE}$[1]	Power-up to Write Operation	100	µs

T10.0 1252

1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.

TABLE 11: Capacitance (T_A = 25°C, f=1 Mhz, other pins open)

Parameter	Description	Test Condition	Maximum
$C_{I/O}$[1]	I/O Pin Capacitance	$V_{I/O}$ = 0V	20 pF
C_{IN}[1]	Input Capacitance	V_{IN} = 0V	16 pF

T11.0 1252

1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.

TABLE 12: Flash Reliability Characteristics

Symbol	Parameter	Minimum Specification	Units	Test Method
N_{END}[1]	Endurance	10,000	Cycles	JEDEC Standard A117
T_{DR}[1]	Data Retention	100	Years	JEDEC Standard A103
I_{LTH}[1]	Latch Up	100 + I_{DD}	mA	JEDEC Standard 78

T12.0 1252

1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.

AC CHARACTERISTICS

TABLE 13: (P)SRAM Read Cycle Timing Parameters

		Min	Max	Units
T_{RCS}	Read Cycle Time	70		ns
T_{AAS}	Address Access Time		70	ns
T_{BES}	Bank Enable Access Time		70	ns
T_{OES}	Output Enable Access Time		35	ns
T_{BYES}	UBS#, LBS# Access Time		70	ns
T_{BLZS}[1]	BES# to Active Output	0		ns
T_{OLZS}[1]	Output Enable to Active Output	0		ns
T_{BYLZS}[1]	UBS#, LBS# to Active Output	0		ns
T_{BHZS}[1]	BES# to High-Z Output		25	ns
T_{OHZS}[1]	Output Disable to High-Z Output		25	ns
T_{BYHZS}[1]	UBS#, LBS# to High-Z Output		35	ns
T_{OHS}	Output Hold from Address Change	10		ns

T13.0 1252

1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.

TABLE 14: (P)SRAM Write Cycle Timing Parameters

Symbol	Parameter	Min	Max	Units
T_{WCS}	Write Cycle Time	70		ns
T_{BWS}	Bank Enable to End-of-Write	60		ns
T_{AWS}	Address Valid to End-of-Write	60		ns
T_{ASTS}	Address Set-up Time	0		ns
T_{WPS}	Write Pulse Width	60		ns
T_{WRS}	Write Recovery Time	0		ns
T_{BYWS}	UBS#, LBS# to End-of-Write	50		ns
T_{ODWS}	Output Disable from WE# Low		30	ns
T_{OEWS}	Output Enable from WE# High	0		ns
T_{DSS}	Data Set-up Time	30		ns
T_{DHS}	Data Hold from Write Time	0		ns

T14.0 1252

TABLE 15: Flash Read Cycle Timing Parameters V_{DD} = 2.7-3.3V

Symbol	Parameter	Min	Max	Units
T_{RC}	Read Cycle Time	70		ns
T_{CE}	Chip Enable Access Time		70	ns
T_{AA}	Address Access Time		70	ns
T_{OE}	Output Enable Access Time		35	ns
T_{CLZ}[1]	BEF# Low to Active Output	0		ns
T_{OLZ}[1]	OE# Low to Active Output	0		ns
T_{CHZ}[1]	BEF# High to High-Z Output		20	ns
T_{OHZ}[1]	OE# High to High-Z Output		20	ns
T_{OH}[1]	Output Hold from Address Change	0		ns
T_{RP}[1]	RST# Pulse Width	500		ns
T_{RHR}[1]	RST# High Before Read	50		ns
T_{RY}[1,2]	RST# Pin Low to Read		20	µs

T15.0 1252

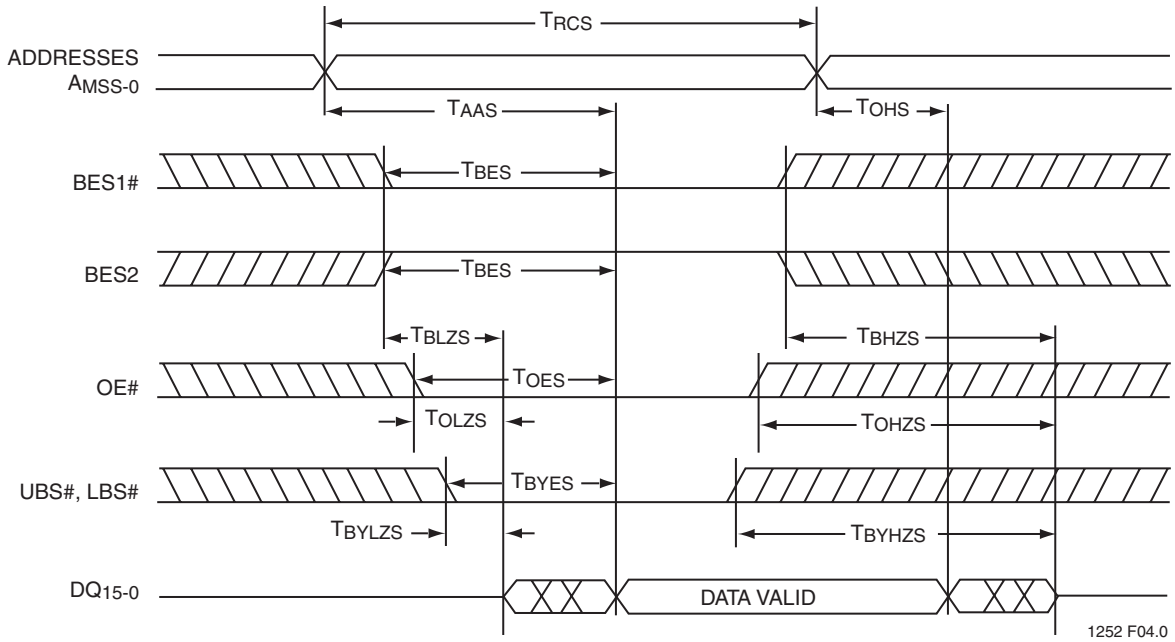
1. This parameter is measured only for initial qualification and after the design or process change that could affect this parameter.
2. This parameter applies to Sector-Erase, Block-Erase and Program operations. This parameter does not apply to Chip-Erase.

TABLE 16: Flash Program/Erase Cycle Timing Parameters

Symbol	Parameter	Min	Max	Units
T_{BP}	Program Time		10	µs
T_{AS}	Address Setup Time	0		ns
T_{AH}	Address Hold Time	40		ns
T_{CS}	WE# and BEF# Setup Time	0		ns
T_{CH}	WE# and BEF# Hold Time	0		ns
T_{OES}	OE# High Setup Time	0		ns
T_{OEH}	OE# High Hold Time	10		ns
T_{CP}	BEF# Pulse Width	40		ns
T_{WP}	WE# Pulse Width	40		ns
T_{WPH}[1]	WE# Pulse Width High	30		ns
T_{CPH}[1]	BEF# Pulse Width High	30		ns
T_{DS}	Data Setup Time	30		ns
T_{DH}[1]	Data Hold Time	0		ns
T_{IDA}[1]	Software ID Access and Exit Time		150	ns
T_{ES}	Erase-Suspend Latency		10	µs
T_{BY}[1,2]	RY/BY# Delay Time	90		ns
T_{BR}[1]	Bus# Recovery Time		1	µs
T_{SE}	Sector-Erase		25	ms
T_{BE}	Block-Erase		25	ms
T_{SCE}	Chip-Erase		50	ms

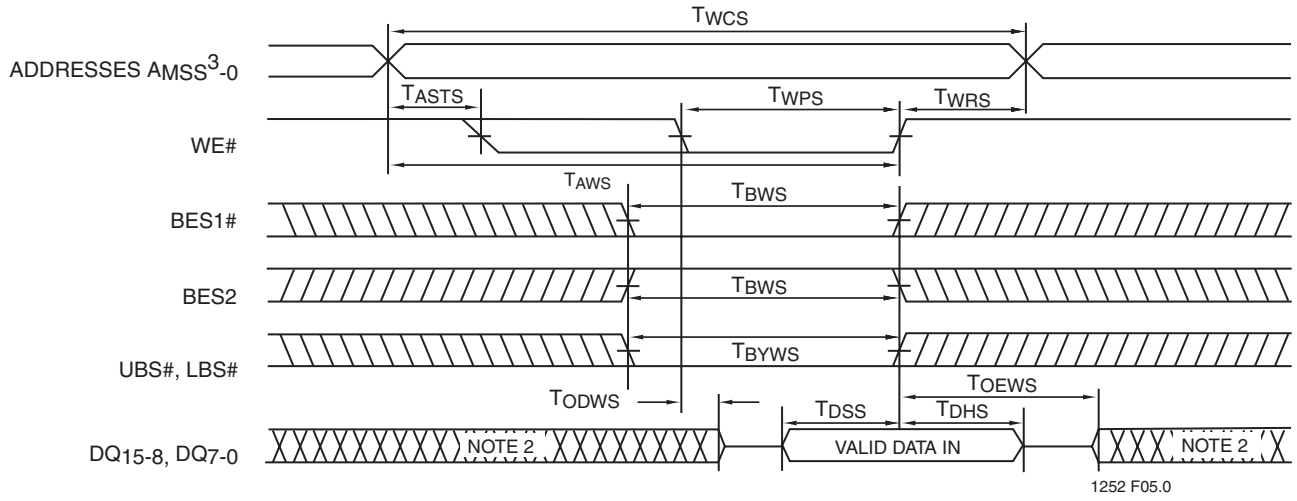
T16.1 1252

1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.
2. This parameter applies to Sector-Erase, Block-Erase, and Program operations.
   This parameter does not apply to Chip-Erase operations.



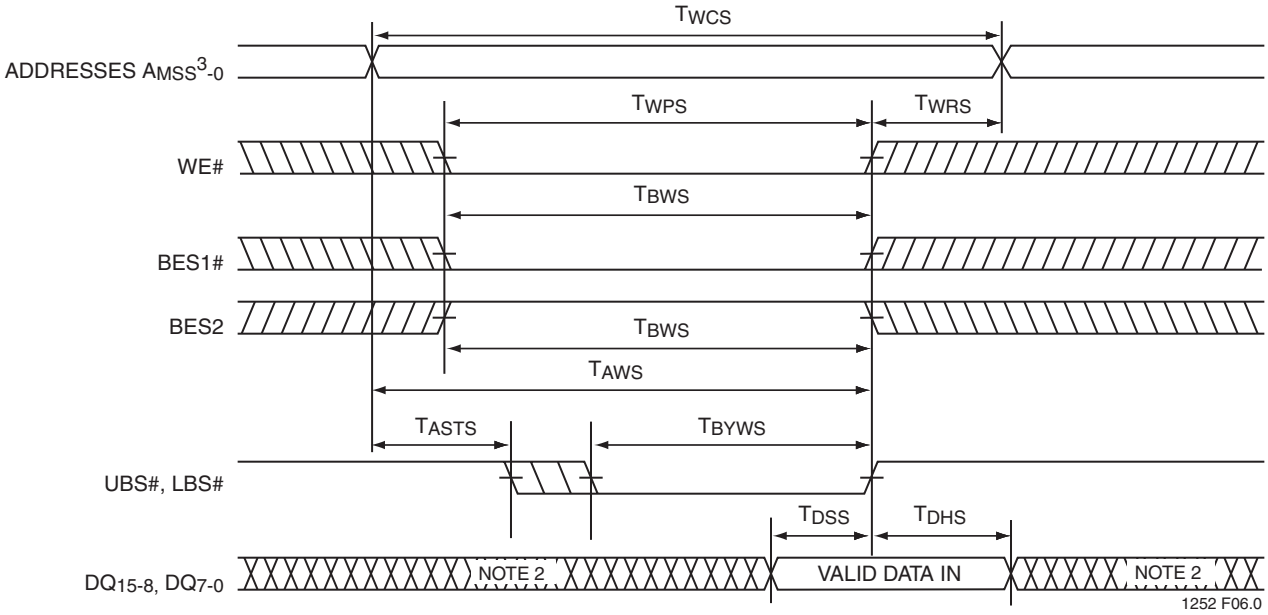
Note: A_{MSS} = Most Significant Address
$A_{MSS} = A_{16}$ for SST34HF1621C, A_{17} for SST34HF1641C/J, and A_{18} for SST34HF1681J

FIGURE 6: (P)SRAM Read Cycle Timing Diagram



Note: 1. If OE# is High during the Write cycle, the outputs will remain at high impedance.
2. If BES1# goes Low or BES2 goes high coincident with or after WE# goes Low, the output will remain at high impedance. If BES1# goes High or BES2 goes low coincident with or before WE# goes High, the output will remain at high impedance. Because D_{IN} signals may be in the output state at this time, input signals of reverse polarity must not be applied.
3. A_{MSS} = Most Significant SRAM Address
$A_{MSS} = A_{16}$ for SST34HF1621C, A_{17} for SST34HF1641C/J, and A_{18} for SST34HF1681J

FIGURE 7: (P)SRAM Write Cycle Timing Diagram (WE# Controlled)[1]



Note: 1. If OE# is High during the Write cycle, the outputs will remain at high impedance.
2. Because D_{IN} signals may be in the output state at this time, input signals of reverse polarity must not be applied.
3. A_{MSS} = Most Significant SRAM Address
A_{MSS} = A_{16} for SST34HF1621C, A_{17} for SST34HF1641C/J, and A_{18} for SST34HF1681J

FIGURE 8: (P)SRAM Write Cycle Timing Diagram (UBS#, LBS# Controlled)[1] x16 (P)SRAM ONLY

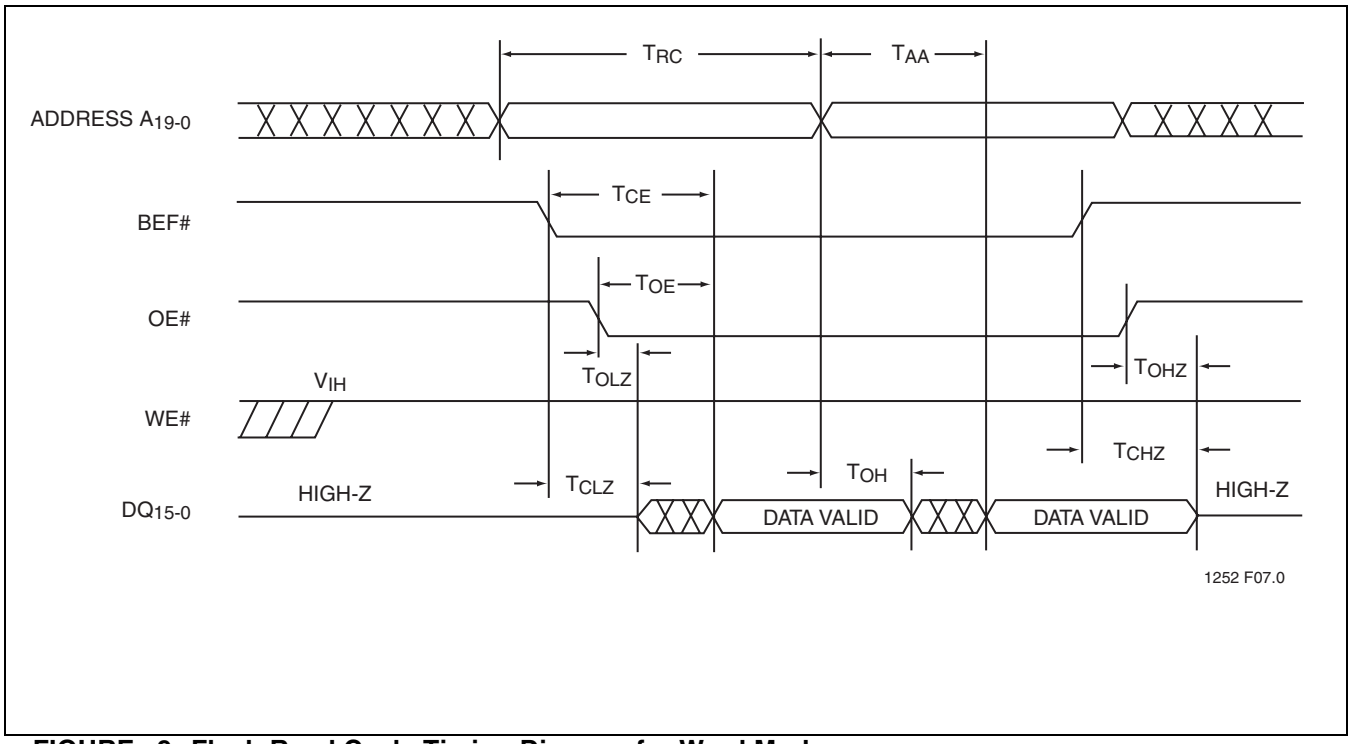
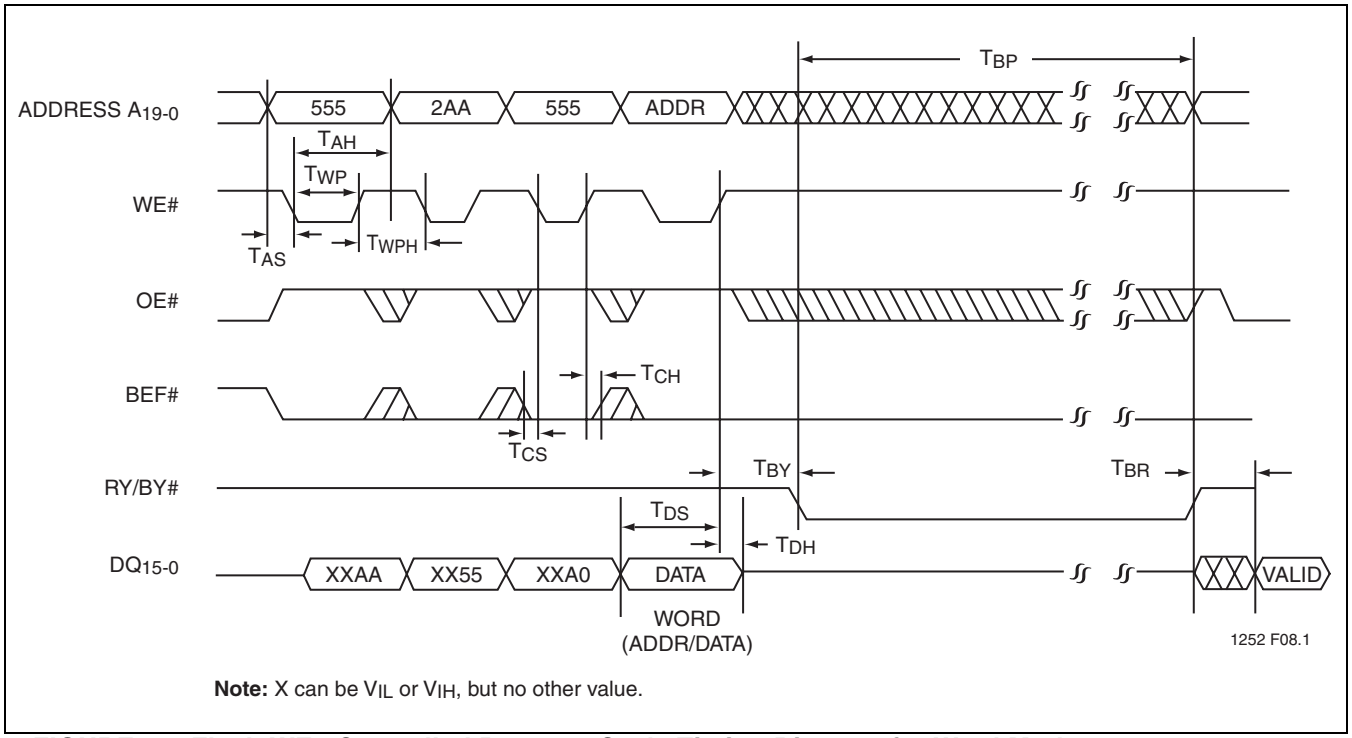
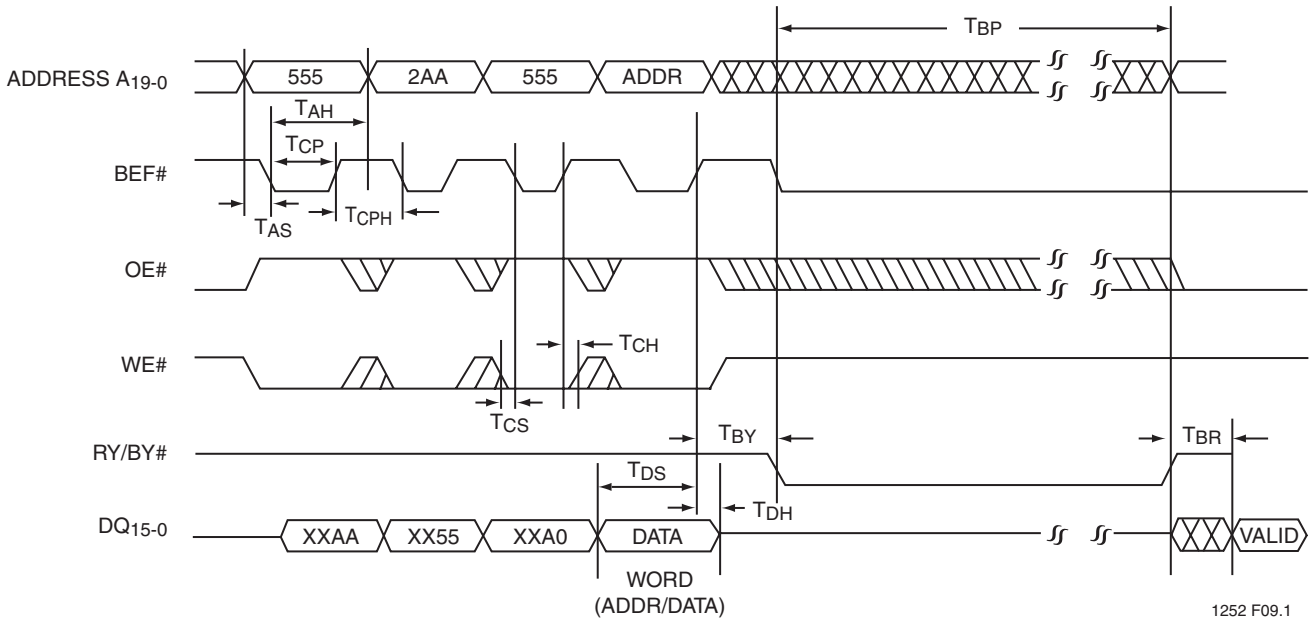


FIGURE 9: Flash Read Cycle Timing Diagram for Word Mode (For Byte Mode A_{-1} = Address Input)



Note: X can be V_{IL} or V_{IH}, but no other value.

FIGURE 10: Flash WE# Controlled Program Cycle Timing Diagram for Word Mode (For Byte Mode A_{-1} = Address Input)



Note: X can be V_{IL} or V_{IH}, but no other value.

FIGURE 11: Flash BEF# Controlled Program Cycle Timing Diagram for Word Mode (For Byte Mode A_{-1} = Address Input)

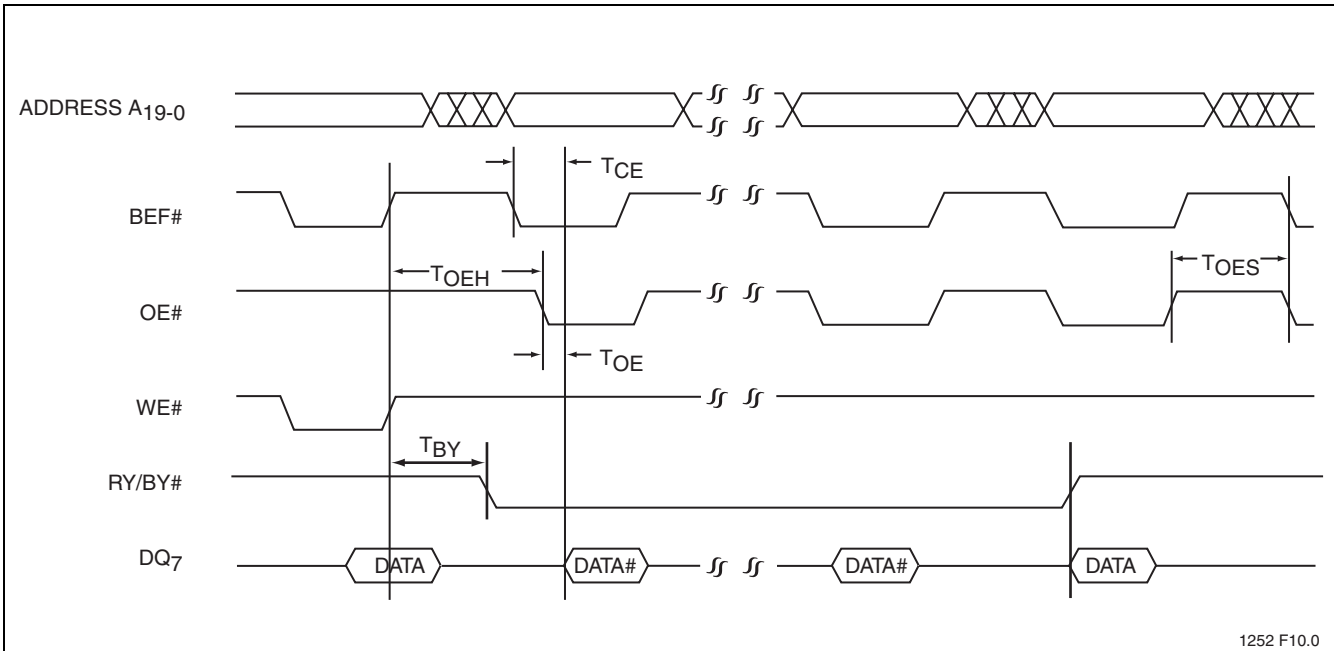


FIGURE 12: Flash Data# Polling Timing Diagram for Word Mode (For Byte Mode A_{-1} = Address Input)

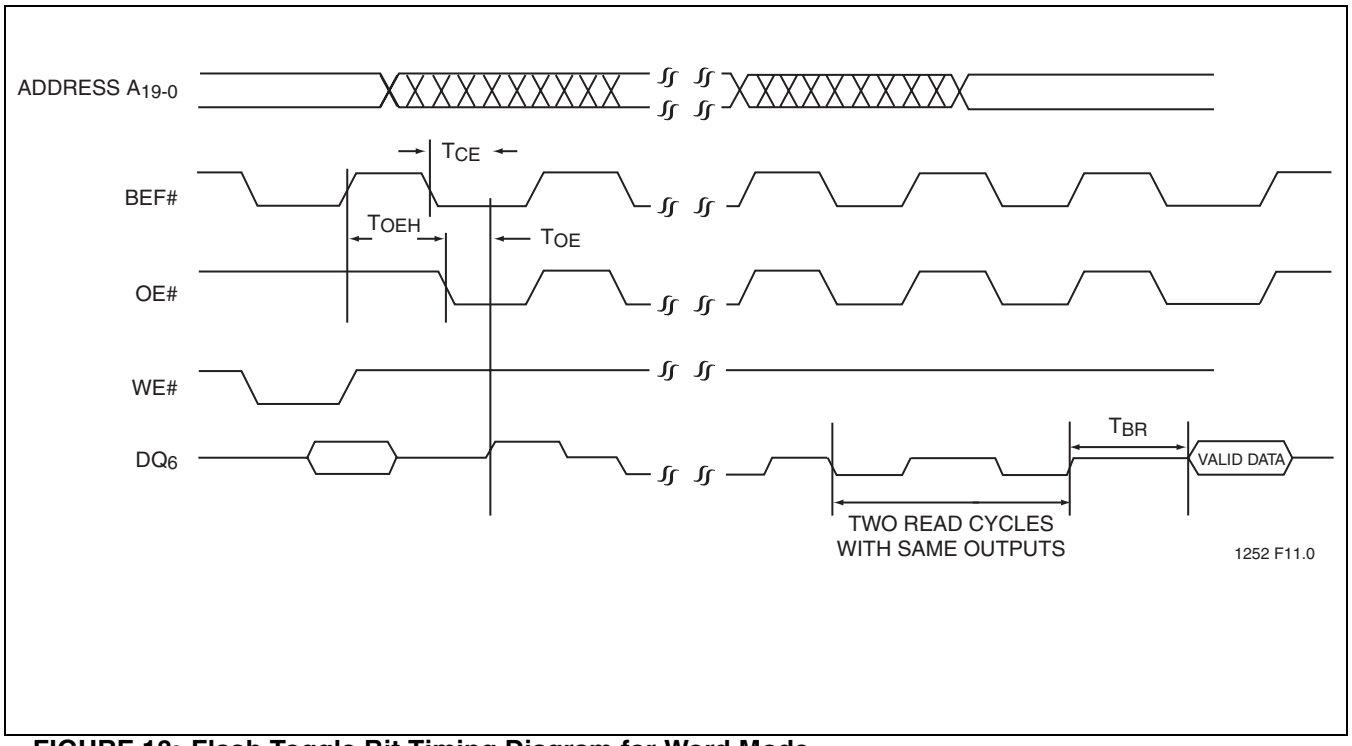
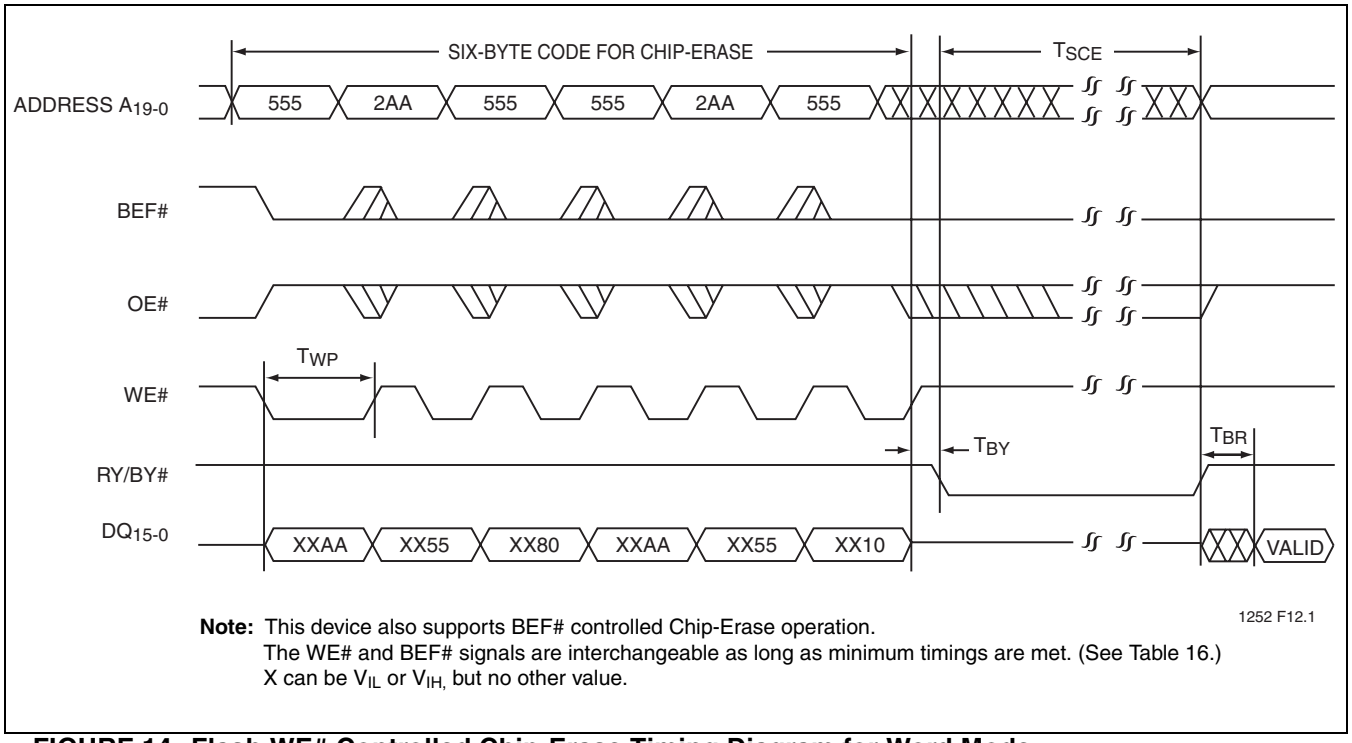
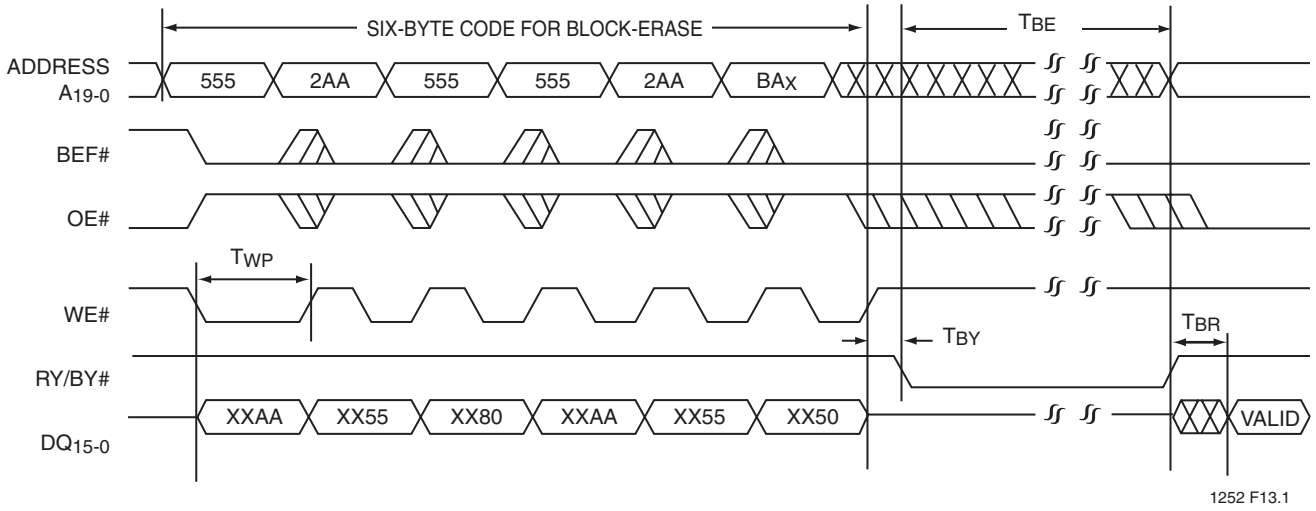


FIGURE 13: Flash Toggle Bit Timing Diagram for Word Mode (For Byte Mode A_{-1} = Don't Care)



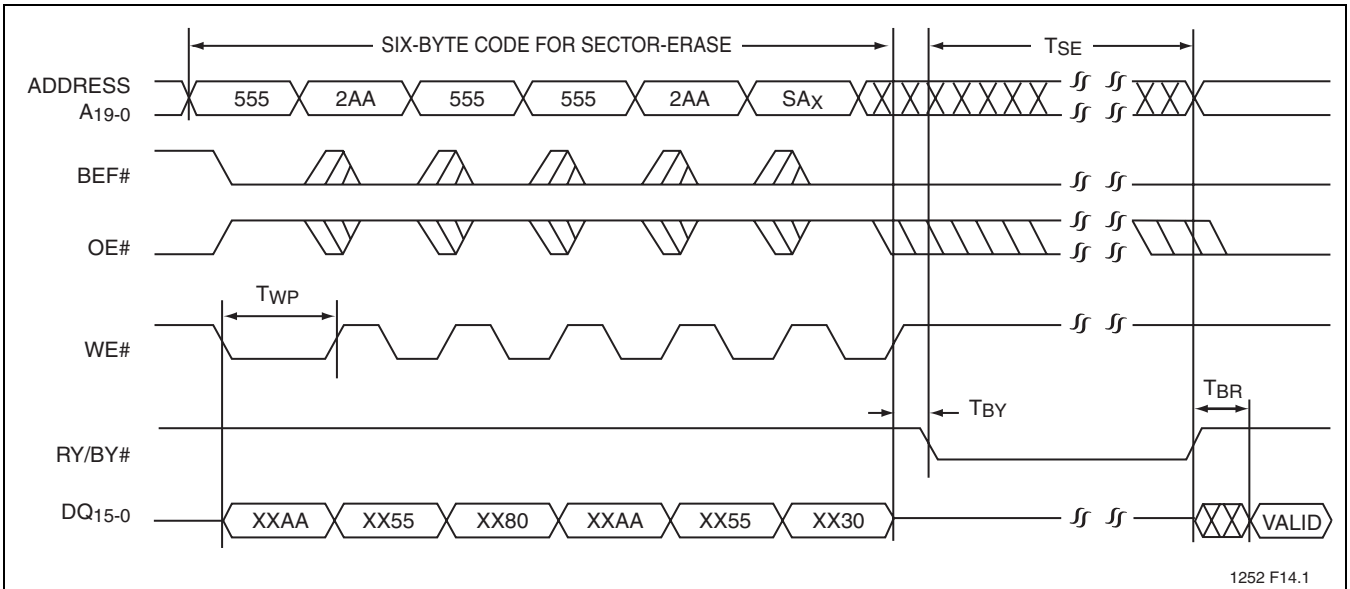
Note: This device also supports BEF# controlled Chip-Erase operation.
The WE# and BEF# signals are interchangeable as long as minimum timings are met. (See Table 16.)
X can be V_{IL} or V_{IH}, but no other value.

FIGURE 14: Flash WE# Controlled Chip-Erase Timing Diagram for Word Mode (For Byte Mode A_{-1} = Don't Care)



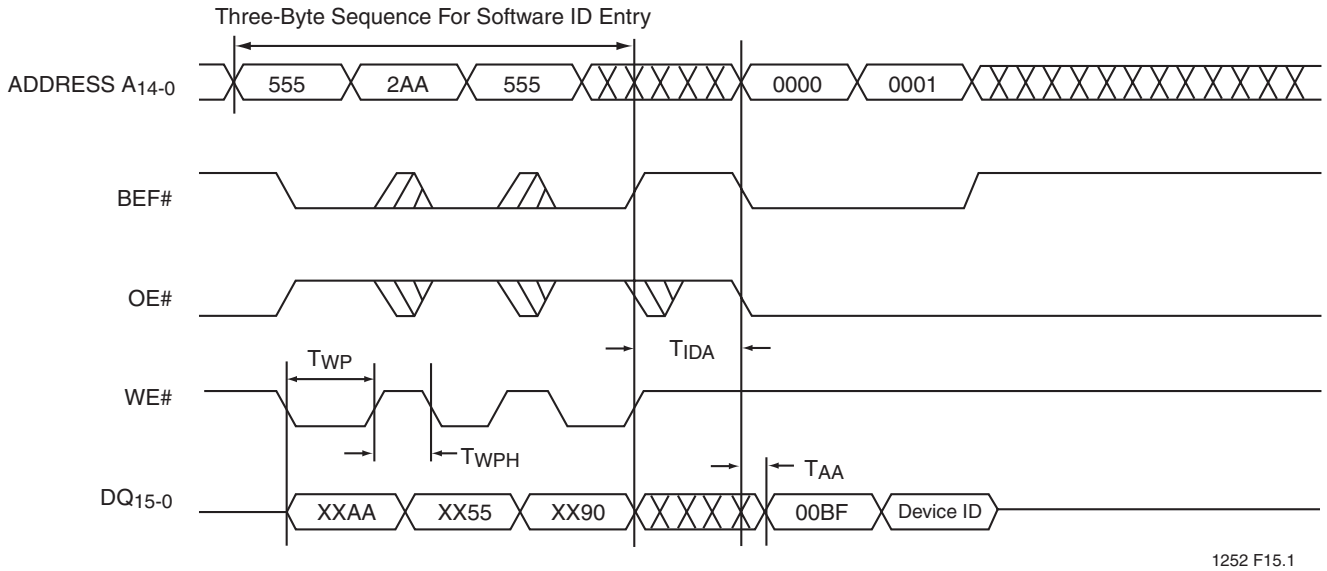
Note: This device also supports BEF# controlled Block-Erase operation.
The WE# and BEF# signals are interchangeable as long as minimum timings are met. (See Table 16.)
BA_X = Block Address
X can be V_{IL} or $V_{IH,}$ but no other value.

FIGURE 15: Flash WE# Controlled Block-Erase Timing Diagram for Word Mode (For Byte Mode A_{-1} = Don't Care)



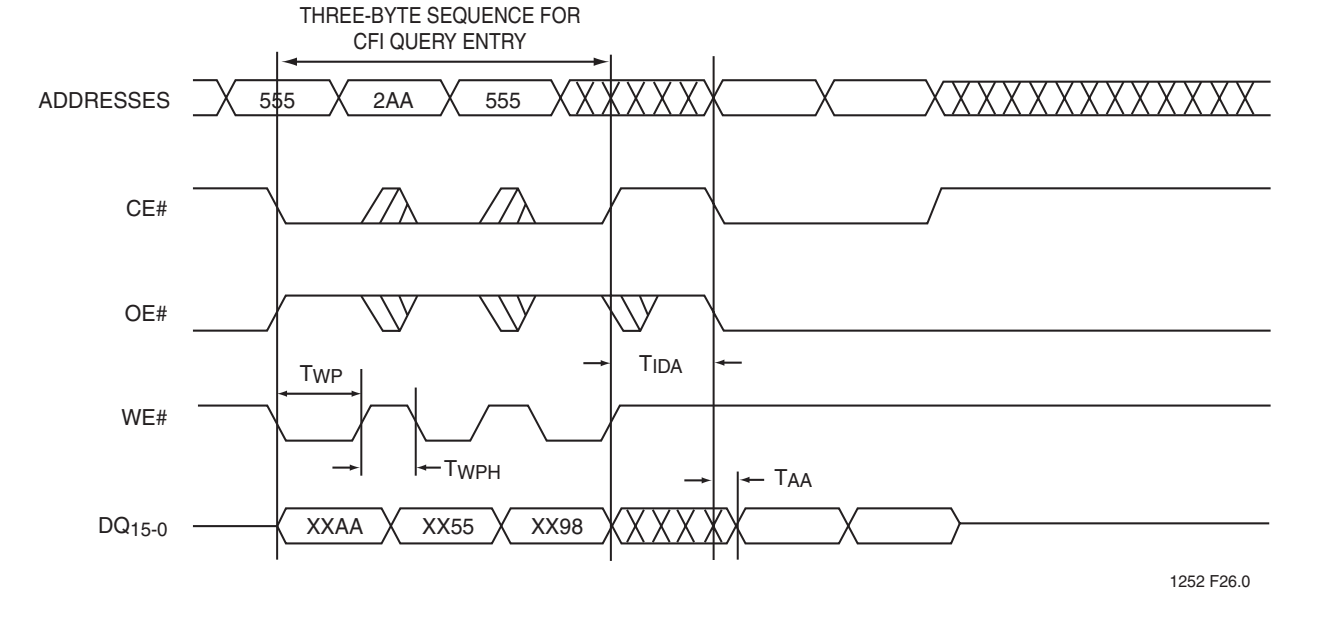
Note: This device also supports BEF# controlled Sector-Erase operation.
The WE# and BEF# signals are interchangeable as long as minimum timings are met. (See Table 16.)
SA_X = Sector Address
X can be V_{IL} or $V_{IH,}$ but no other value.

FIGURE 16: Flash WE# Controlled Sector-Erase Timing Diagram for Word Mode (For Byte Mode A_{-1} = Don't Care)



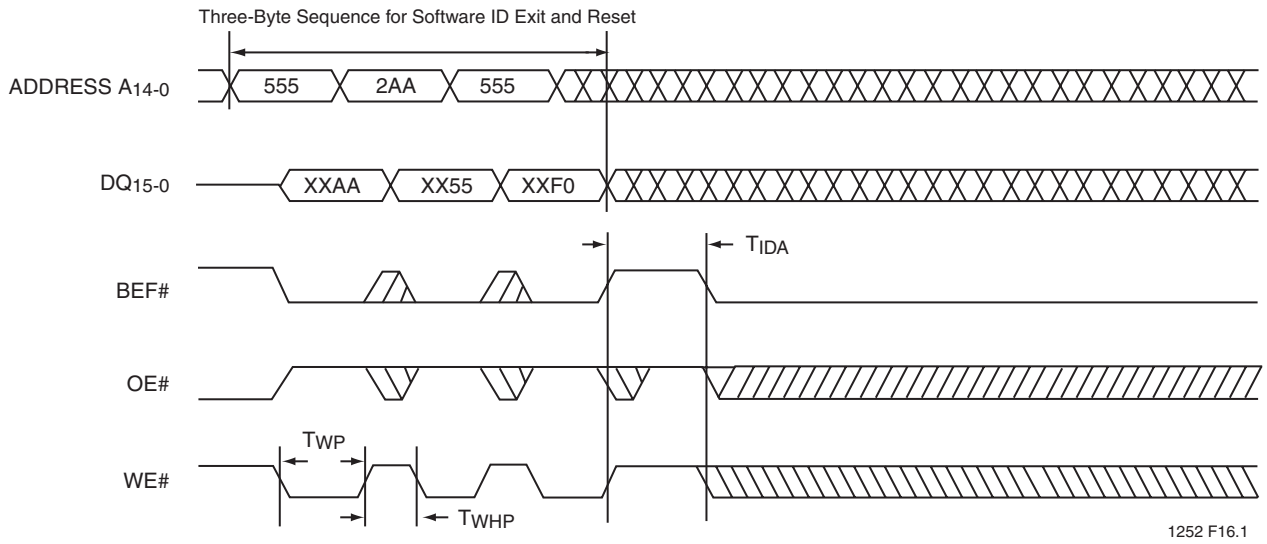
Note: X can be V_{IL} or $V_{IH,}$ but no other value.
Device ID - 734BH for SST34HF16x1C/J

FIGURE 17: Flash Software ID Entry and Read for Word Mode (For Byte Mode A_{-1} = 0)



Note: X can be V_{IL} or $V_{IH,}$ but no other value.

FIGURE 18: CEI Entry and Read



Note: X can be V_{IL} or V_{IH}, but no other value

FIGURE 19: Flash Software ID Exit/CEI Exit for Word Mode (For Byte Mode A_{-1} = 0)

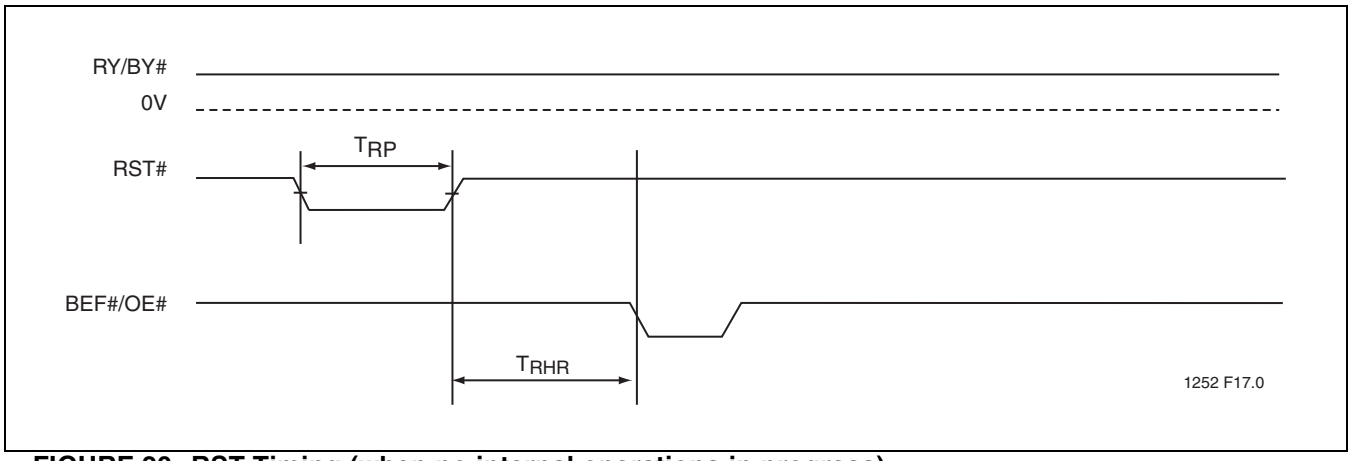


FIGURE 20: RST Timing (when no internal operations in progress)

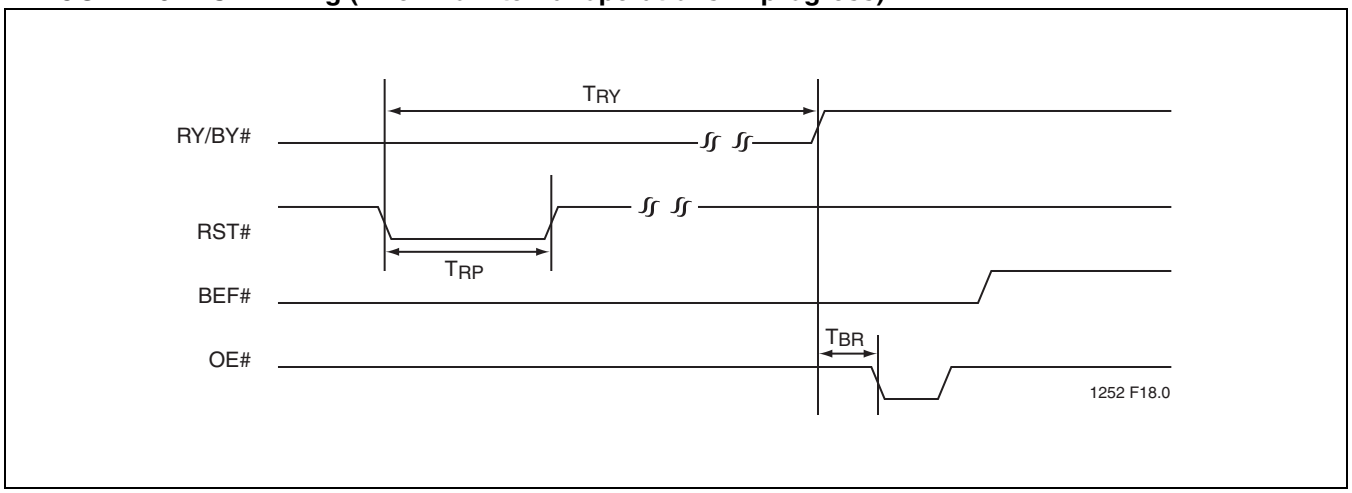
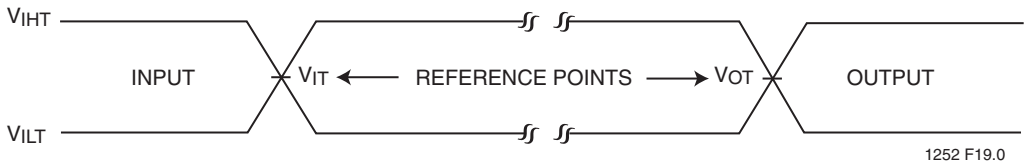


FIGURE 21: RST# Timing (during Sector- or Block-Erase operation)



AC test inputs are driven at V_{IHT} (0.9 V_{DD}) for a logic "1" and V_{ILT} (0.1 V_{DD}) for a logic "0". Measurement reference points for inputs and outputs are V_{IT} (0.5 V_{DD}) and V_{OT} (0.5 V_{DD}). Input rise and fall times (10% ↔ 90%) are <5 ns.

Note: V_{IT} - V_{INPUT} Test
V_{OT} - V_{OUTPUT} Test
V_{IHT} - V_{INPUT} HIGH Test
V_{ILT} - V_{INPUT} LOW Test

FIGURE 22: AC Input/Output Reference Waveforms

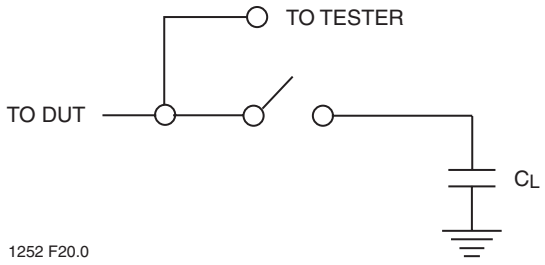
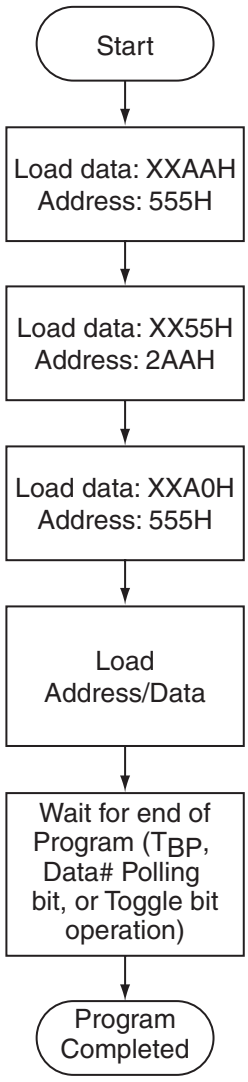


FIGURE 23: A Test Load Example



Note: X can be V_{IL} or V_{IH}, but no other value.

FIGURE 24: Program Algorithm

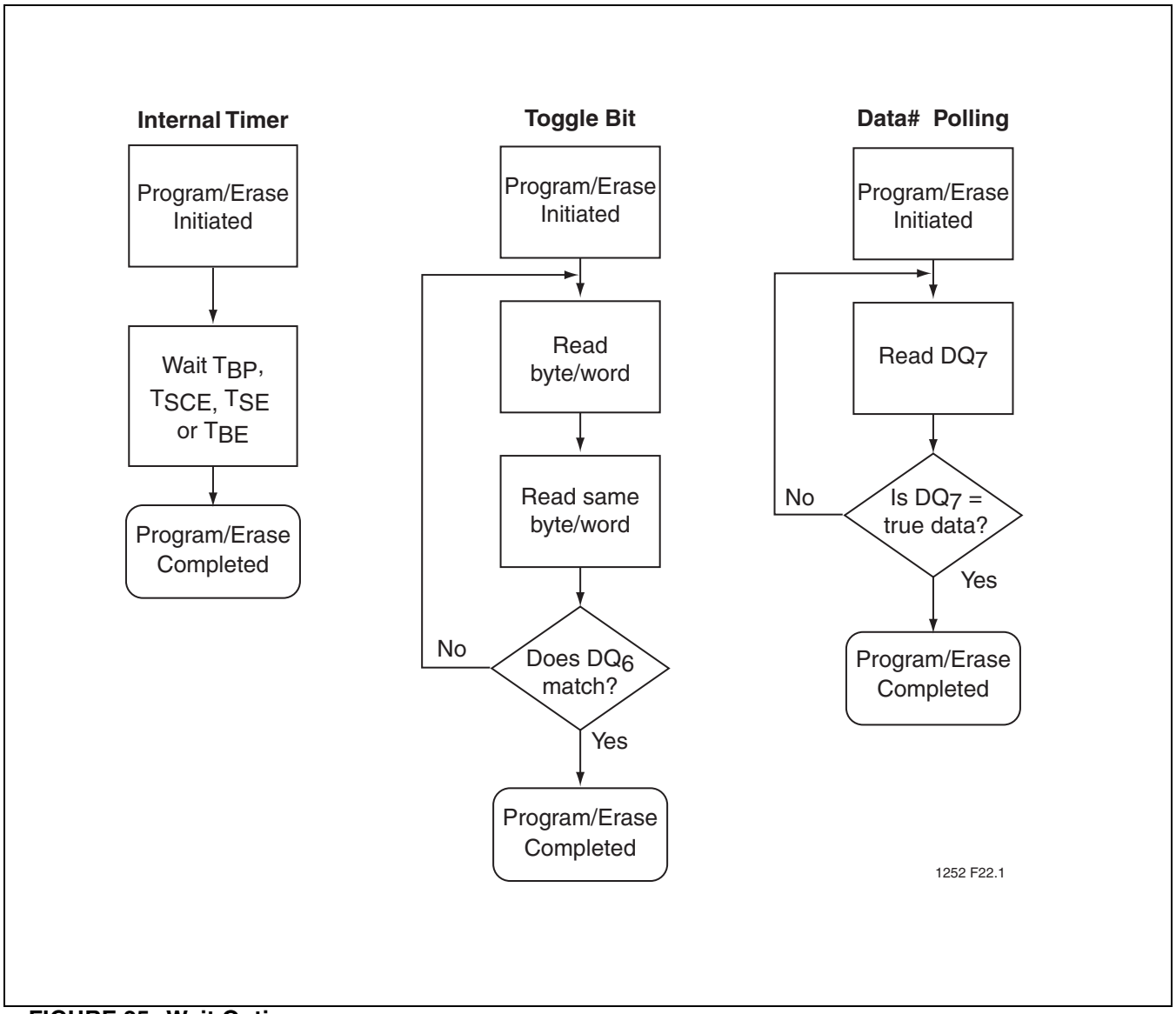


FIGURE 25: Wait Options

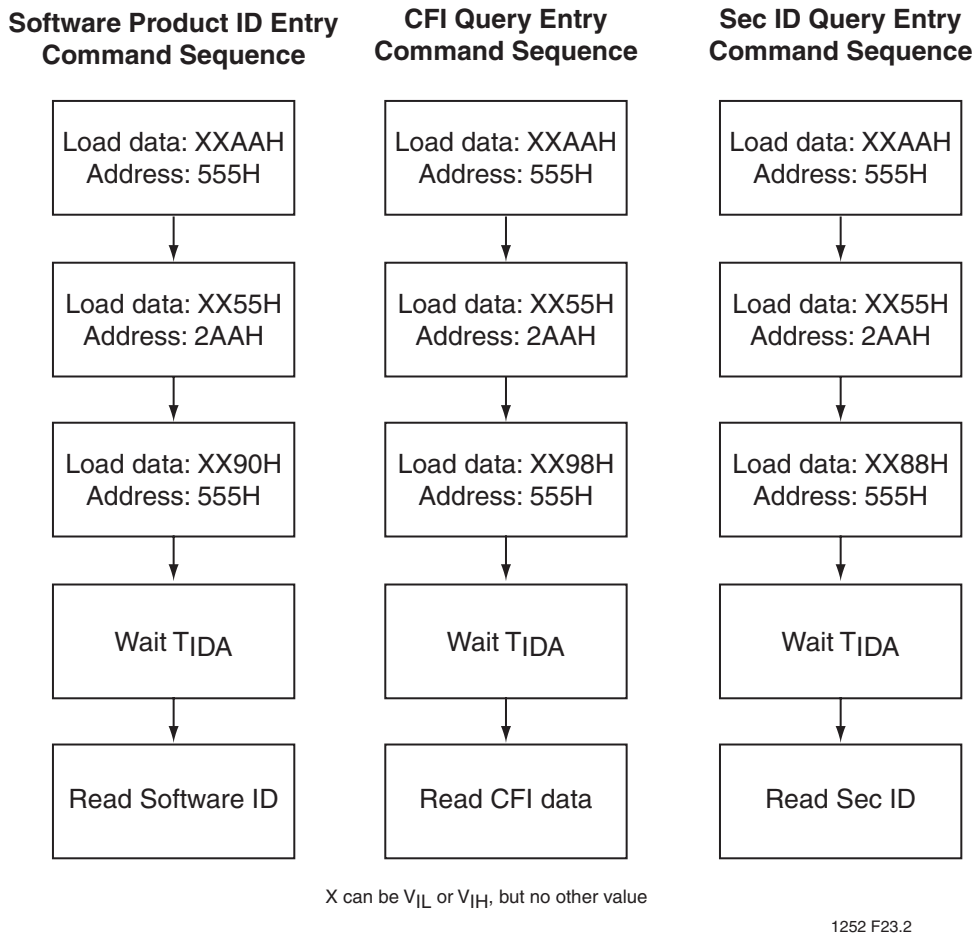


FIGURE 26: Software Product ID/CFI/Sec ID Command Flowcharts

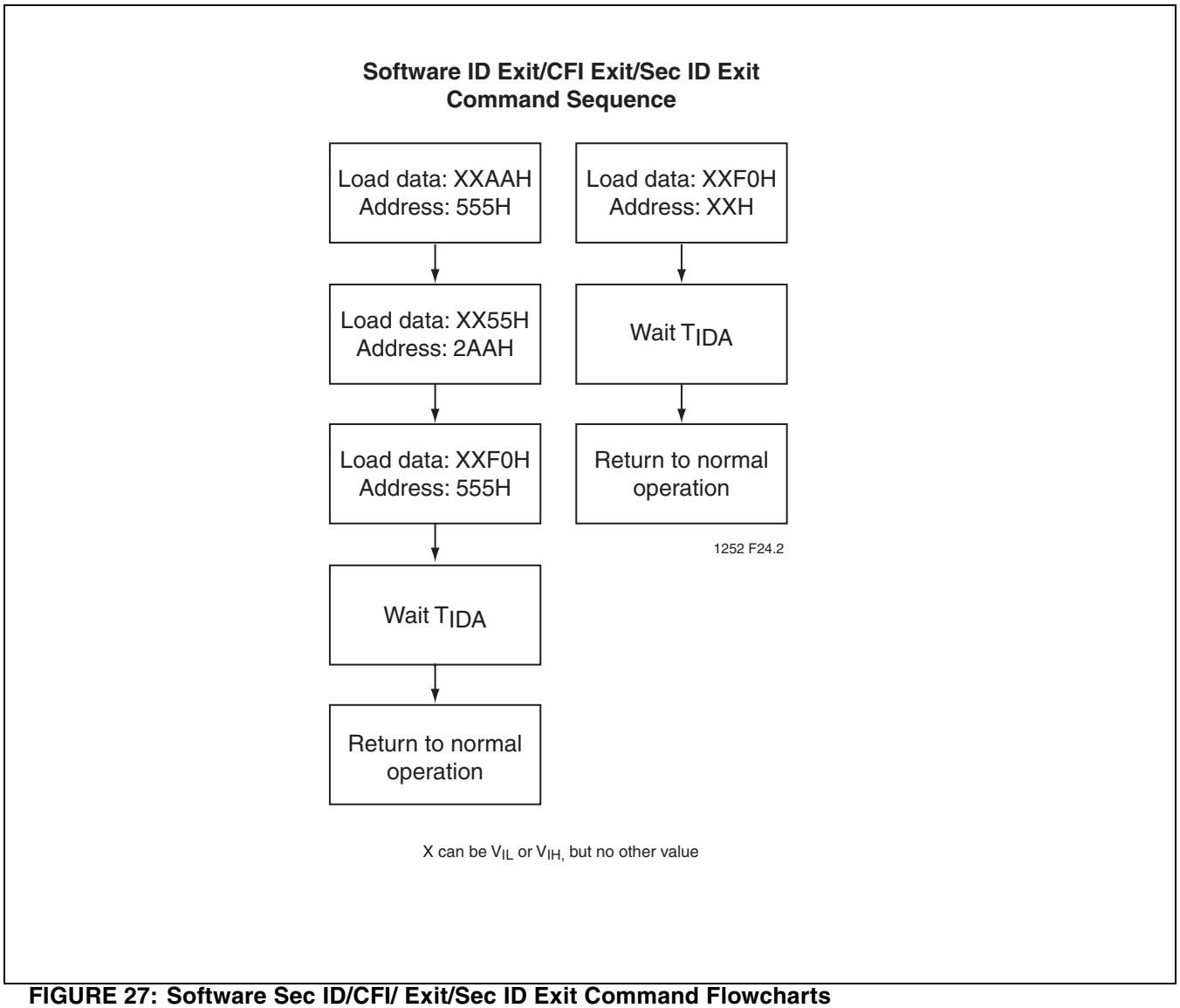
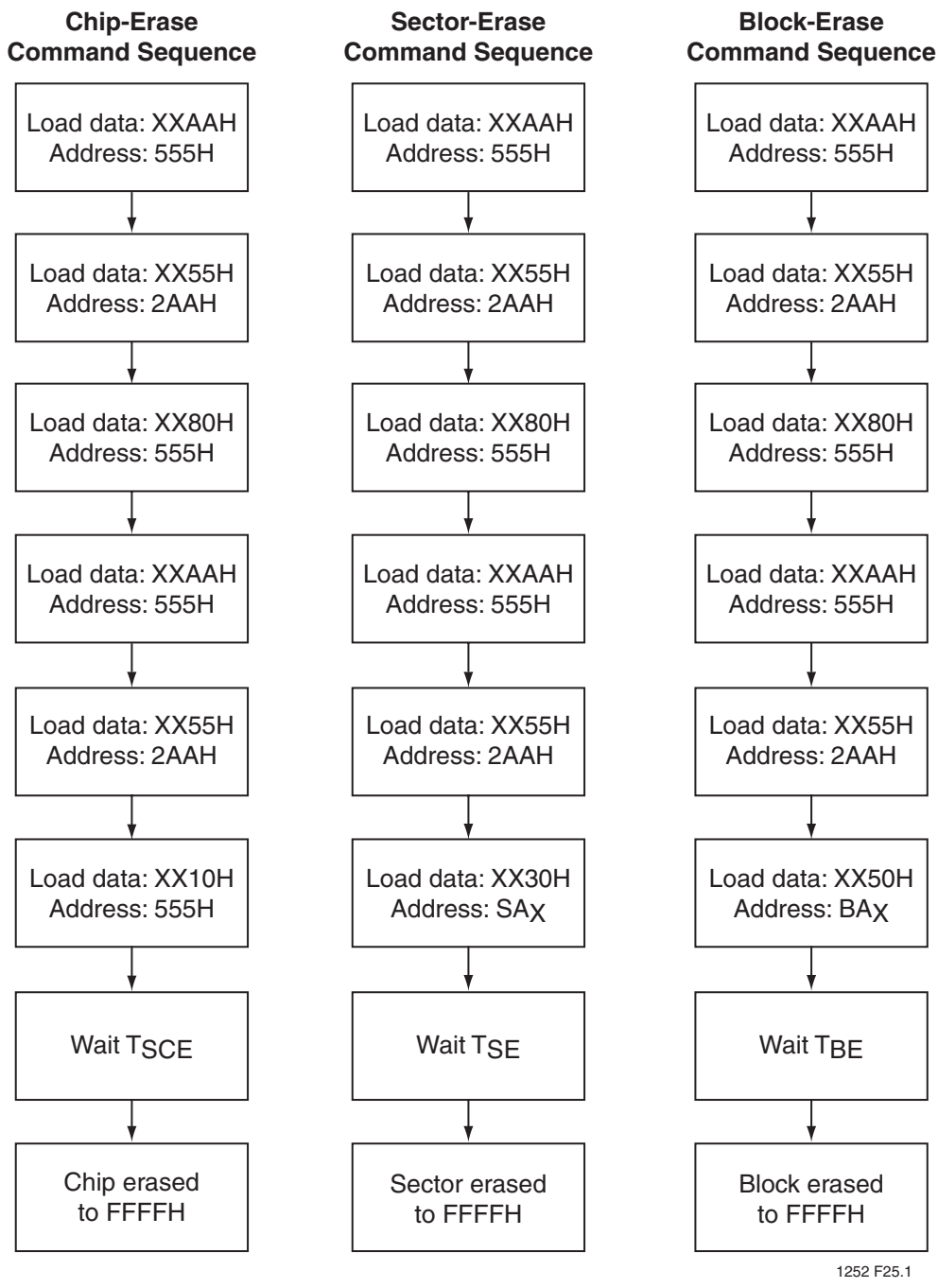


FIGURE 27: Software Sec ID/CFI/ Exit/Sec ID Exit Command Flowcharts



Note: X can be V_{IL} or V_{IH}, but no other value.

FIGURE 28: Erase Command Sequence

PRODUCT ORDERING INFORMATION

Device **Speed** **Suffix1** **Suffix2**

SST34HF16x1X- XXX - XX - XXXX

Package Attribute
E[1] = non-Pb

Package Modifier
P = 56 balls
S = 62 balls

Package Type
L1 = LFBGA (8mm x 10mm x 1.4mm, 0.45mm ball size)
L = LFBGA (8mm x 10mm x 1.4mm, 0.40mm ball size)

Temperature Range
E = Extended = -20°C to +85°C

Minimum Endurance
4 =10,000 cycles

Read Access Speed
70 = 70 ns

Version
C = x16 Mbit SRAM
J = x16 Mbit PSRAM

Boot Block Protection
1 = Bottom Boot Block

(P)SRAM Density
2 = 2 Mbit
4 = 4 Mbit
8 = 8 Mbit

Flash Density
16 = 16 Mbit

Voltage
H = 2.7-3.3V

Product Series
34 = Concurrent SuperFlash + (P)SRAM ComboMemory

1. Environmental suffix “E” denotes non-Pb solder. SST non-Pb solder devices are “RoHS Compliant”.

Valid combinations for SST34HF1621C

SST34HF1621C-70-4E-L1PE SST34HF1621C-70-4E-LSE

Valid combinations for SST34HF1641C

SST34HF1641C-70-4E-L1PE SST34HF1641C-70-4E-LSE

Valid combinations for SST34HF1641J

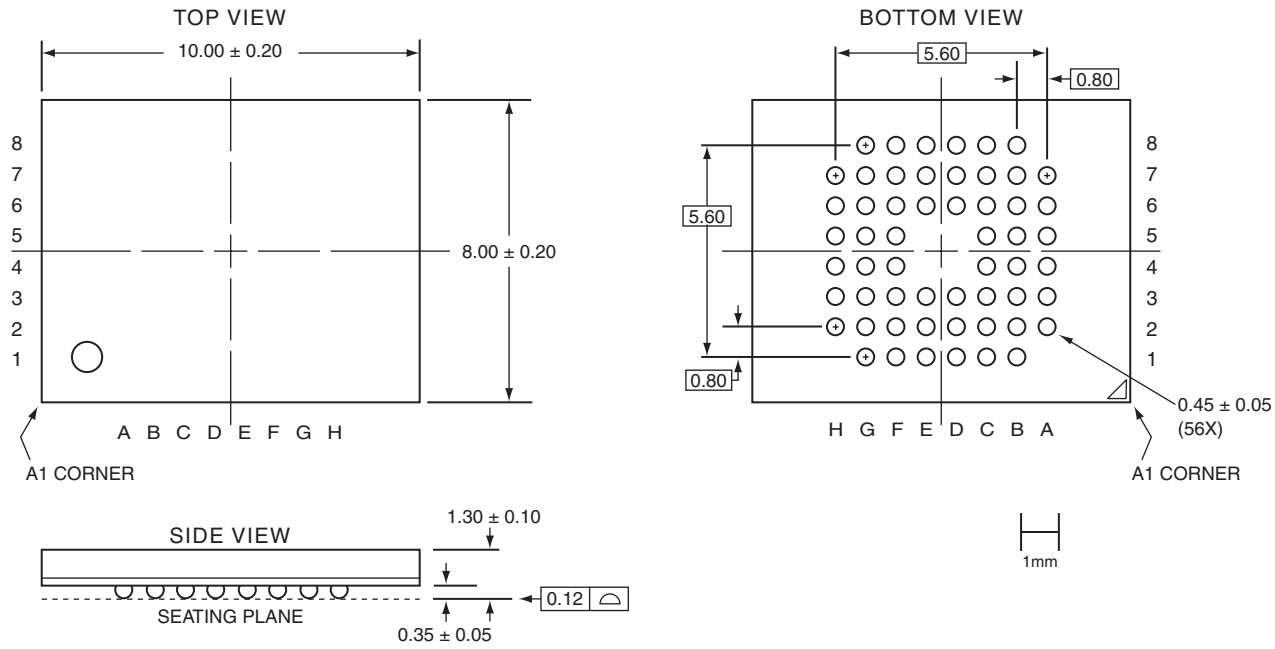
SST34HF1641J-70-4E-L1PE SST34HF1641J-70-4E-LSE

Valid combinations for SST34HF1681J

SST34HF1681J-70-4E-L1PE SST34HF1681J-70-4E-LSE

Note: Valid combinations are those products in mass production or will be in mass production. Consult your SST sales representative to confirm availability of valid combinations and to determine availability of new combinations.

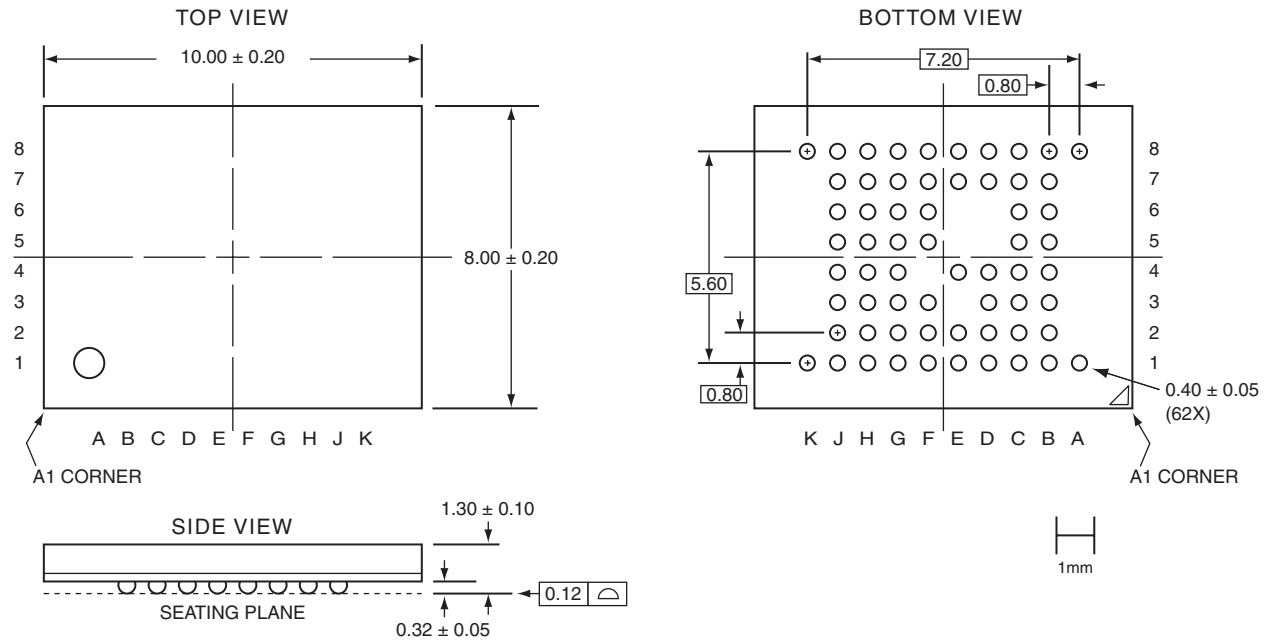
PACKAGING DIAGRAMS



Note: 1. Although many dimensions are similar to those of JEDEC Publication 95, MO-210, this specific package is not registered.
2. All linear dimensions are in millimeters.
3. Coplanarity: 0.12 mm
4. Ball opening size is 0.38 mm (± 0.05 mm)

56-lfbga-L1P-8x10-450mic-4

FIGURE 29: 56-Ball Low-Profile, Fine-Pitch Ball Grid Array (LFBGA) 8mm x 10mm
SST Package Code: L1PE



Note: 1. Although many dimensions are similar to those of JEDEC Publication 95, MO-210, this specific package is not registered.
2. All linear dimensions are in millimeters.
3. Coplanarity: 0.12 mm
4. Ball opening size is 0.32 mm (± 0.05 mm)

62-lfbga-LS-8x10-400mic-4

FIGURE 30: 62-Ball Low-Profile, Fine-Pitch Ball Grid Array (LFBGA) 8mm x 10mm
SST Package Code: LSE

TABLE 17: Revision History

Number	Description	Date
00	• Initial Release	Mar 2004
01	• Renamed all devices previously released with version “D” to “J” • Removed 8 Mbit x8 PSRAM organization for SST34HF1681J • Changed references to Word-Program and Byte-Program to Program • Updated “Flash Erase-Suspend/-Resume Operations” on page 3 • Added RoHS compliance information on page 1 and in the “Product Ordering Information” on page 37 • Removed all references to, and MPNs for, SST34HF1601C to EOL Data Sheet • Removed all references to, and MPNs for, SST34HF1601S • Moved all references to, and MPNs for, SST34HF1601S to S71301 • Updated software command sequence addresses in Table 5 on page 13, timing diagrams, and flowcharts • Added the solder reflow temperature to the “Absolute Maximum Stress Ratings” on page 17 • Corrected footnote 5 in Table 6 “Software Command Sequence” on page 14 • Added Table 7, “CFI Query Identification String” on page 15 • Added Table 8, “System Interface Information” on page 15 • Added Table 9, “Device Geometry Information” on page 16 • Changed I_{DD} test condition for frequency specification from $1/T_{RC}$ Min to 5 MHz See Table 9 on page 17 • Updated TES parameter from 20 µs to 10 µs in Table 17 on page 21	Nov 2005
02	• Removed all occurrences of 256K x8 • Removed x8 SRAM Read and Write cross reference on page 6 • Removed x8 SRAM from Figure 1 Functional Block Diagram page 7 • Removed SRAM x8 Address from Table 3 on page 11 • Removed Table 5 Operational Modes Selection for x8 SRAM • Applied new style formats throughout	Feb 2006